



2018 Interim Results Announcement

July 25, 2018



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ASMPT Recognized as TOP 100 Global Tech Leaders



“The Top 100 Global Technology Leaders are the organizations poised to propel the future of technology”,
Brian Scanlon, Chief Strategy Officer

Thomson Reuters, 2018

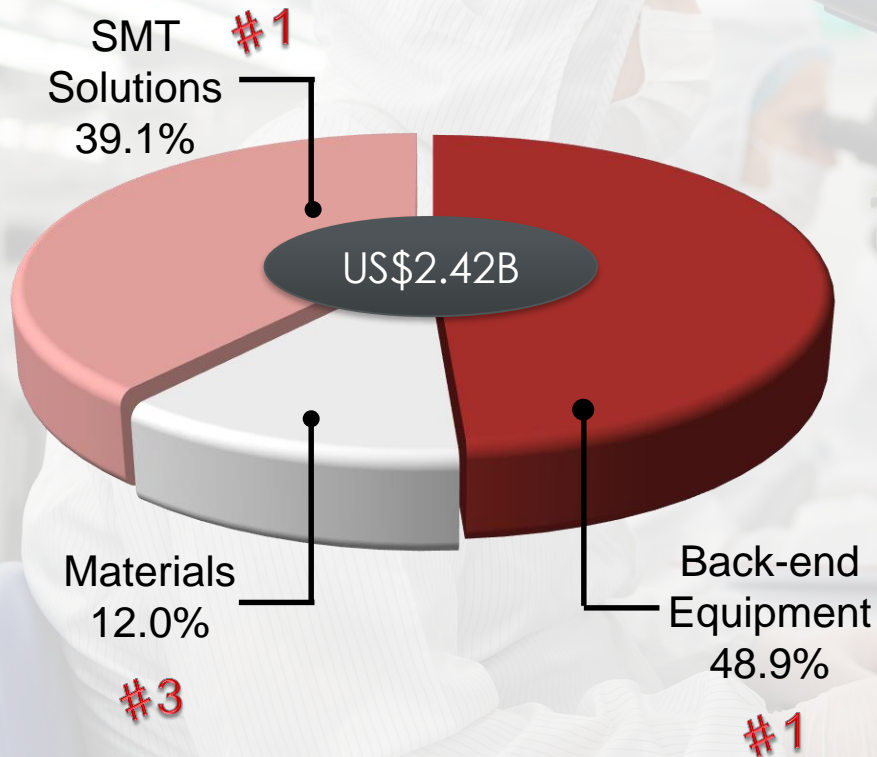
The **ONLY** Back-end Equipment Supplier Being Recognized

CORPORATE OVERVIEW



A World's Technology & Market Leader

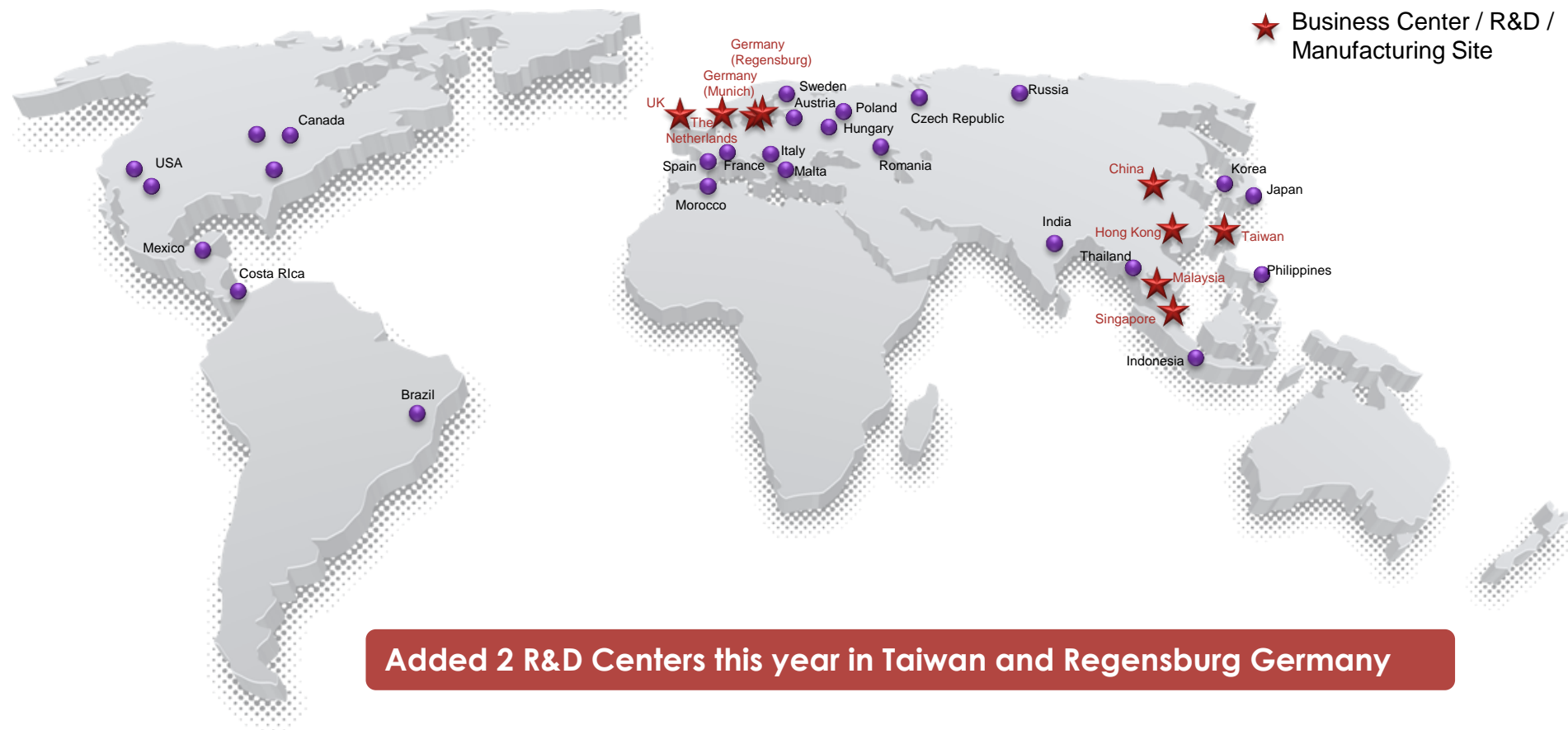
Q2 2018 LTM Group Revenue (CAGR 2008- Q2 2018 LTM 13.7 %)



- A leading Integrated Solutions Provider in the semiconductor assembly and packaging industry as well as in the SMT solutions market
- A leading player for CIS, LED, and Automotive
- 3 high growth markets accounted for 50% of group revenue in 1H2018



ASMPT Global Presence



Added 2 R&D Centers this year in Taiwan and Regensburg Germany



> 1,800
global R&D staff



> 1,100
patents on key leading
edge technologies

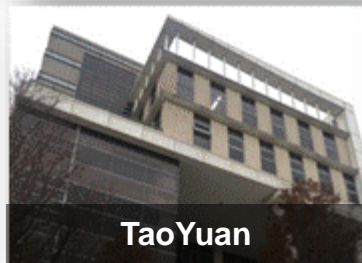


8
R&D centers
worldwide



11
manufacturing
facilities

ASMPT Major Facilities around the World



Three Business Segments With Leading Market Positions

Worldwide Market Position & Share

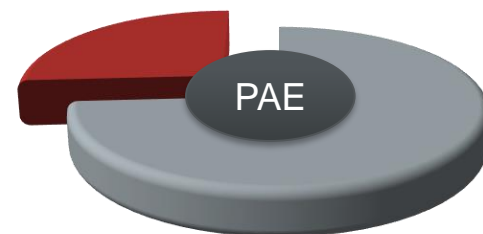
**Back-end
Equipment**

#1

**Assembly & Packaging
Equipment Market**

~25%
(2017)

- #1 Die Bonders
- #2 Wire Bonders
- #1/2 Flip Chip Bonders
- #1 Thermal Compression Bonders (TCB)
- #1 LED Packaging Equipment
- #1 CMOS Imaging Sensors (CIS) Equipment
- #2 Encapsulation & Post Encapsulation Solutions
- #4 Turret Test Equipment (Test Handlers)
- #2 Laser Dicing and Grooving

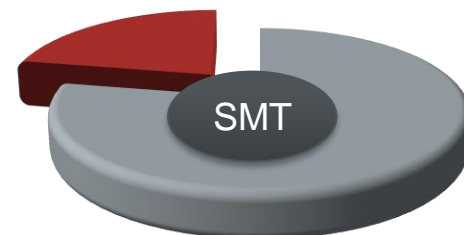


**SMT
Solutions**

#1

SMT Equipment Market

~22%
(2017)



Materials

#3

Leadframe Market

~8.7%
(2017)



Sources:

Market share for Back-end Equipment is based on information on packaging and assembly equipment market by VLSI, leadframe market by SEMI, and SMT market by ASMPT SIPLACE Market Intelligence

2018 1H/Q2 Highlights



Strong 1H/Q2 2018 Bookings/Billings Growth

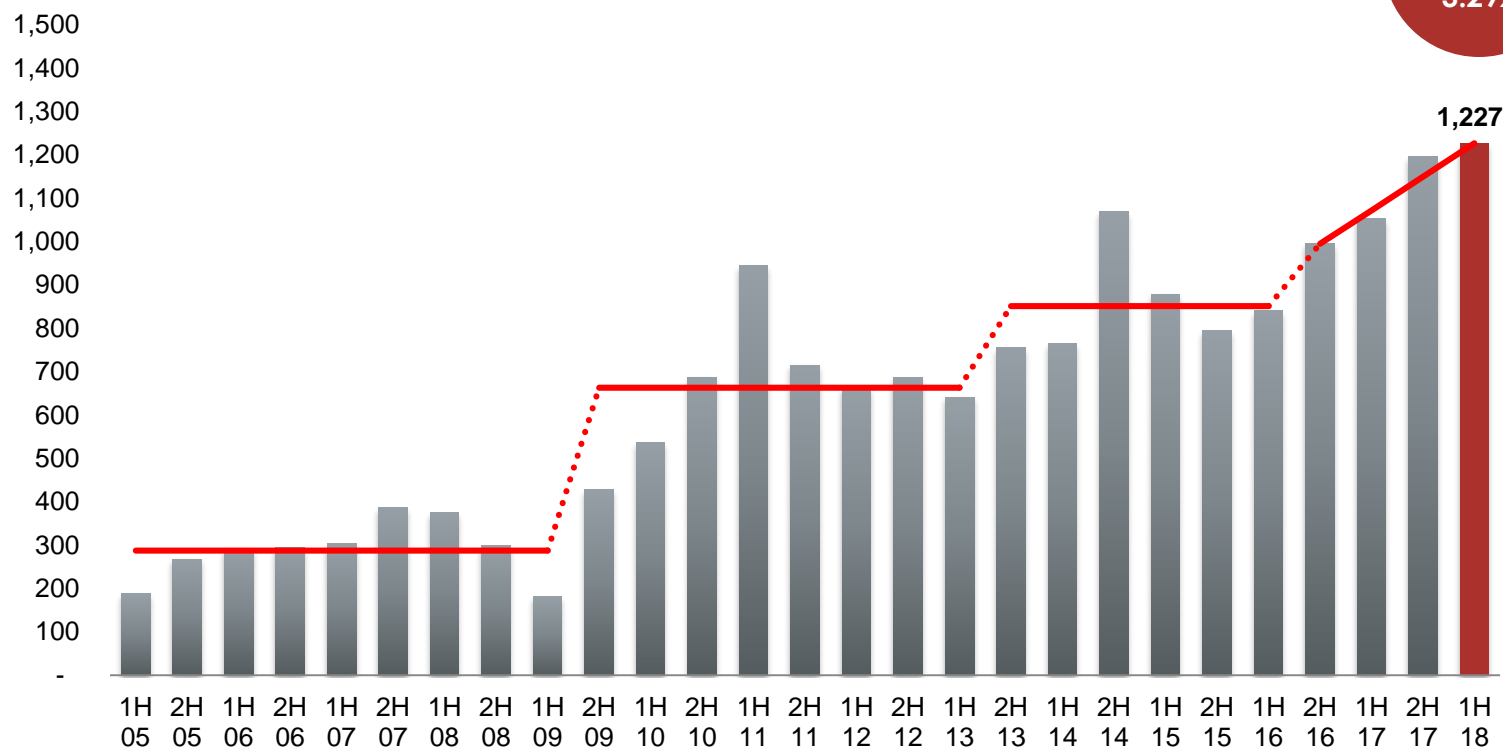
	1H Bookings		1H Billings	
	YoY	HoH	YoY	HoH
Back-end Equipment	↑ 16.9%	↑ 60.9%	↑ 14.4%	↑ 20.1%
Materials	↓ 7.5%	↑ 12.6%	↑ 12.1%	↑ 8.7%
SMT Solutions	↑ 25.3%	↑ 22.9%	↑ 24.6%	↓ 16.4%
Group	↑ 16.7%	↑ 38.4%	↑ 17.5%	↑ 3.0%

	Q2 Bookings		Q2 Billings	
	YoY	QoQ	YoY	QoQ
Back-end Equipment	↑ 8.4%	↓ 12.9%	↑ 17.6%	↑ 28.8%
Materials	↑ 3.3%	↑ 5.5%	↑ 7.1%	↑ 2.1%
SMT Solutions	↑ 14.1%	↑ 8.0%	↑ 26.3%	↑ 17.8%
Group	↑ 10.1%	↓ 3.5%	↑ 19.1%	↑ 21.3%

ASMPT Entering a High Growth Period

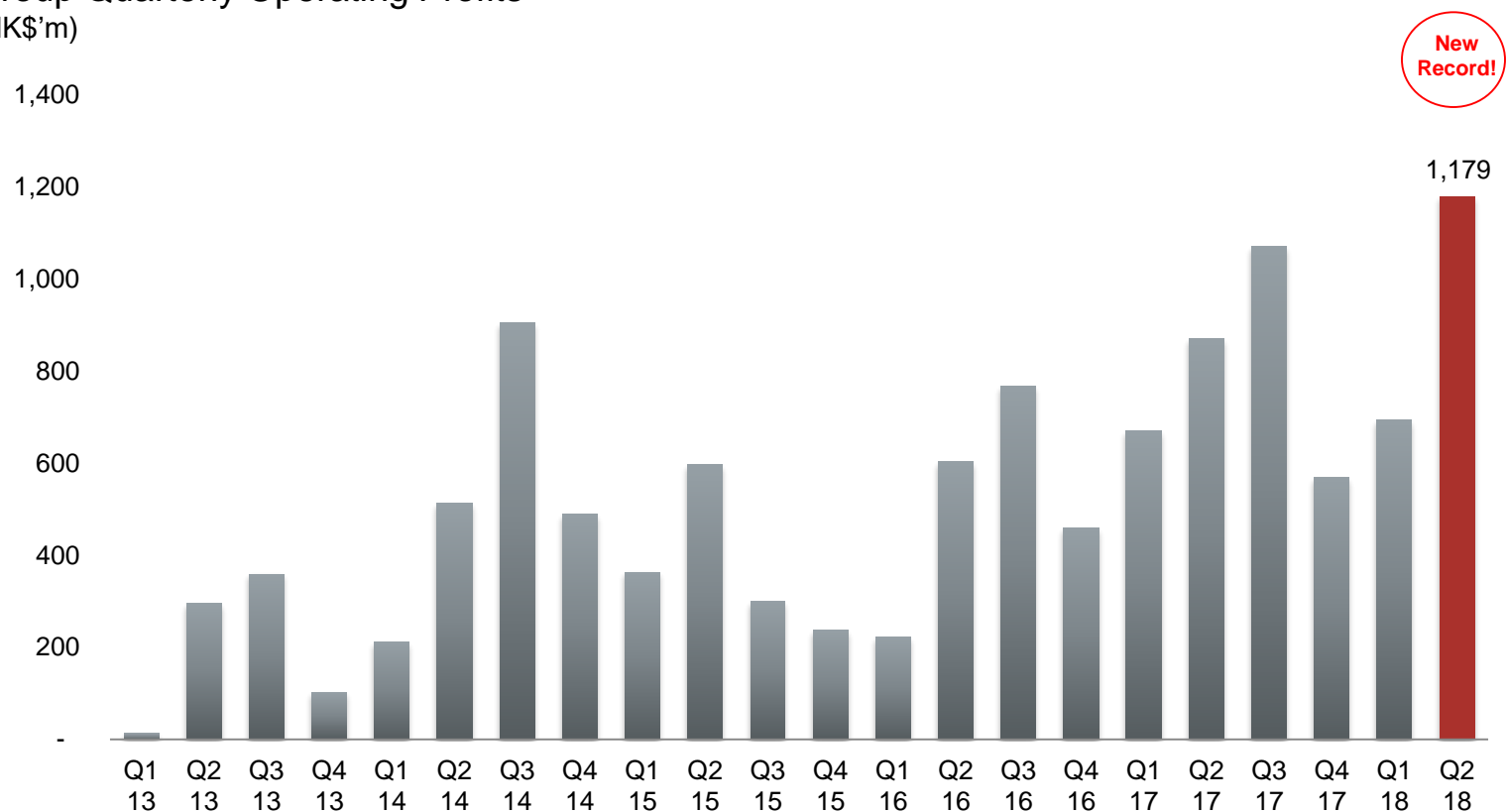
Group Half Yearly Billings
(US\$ m)

1H18 Rev
vs 1H08
3.29x



Record High Quarterly Operating Profits

Group Quarterly Operating Profits
(HK\$m)



Major Drivers for Strong 1H 2018 Bookings

Back-end

IC /
Discrete

Power
Management



IoT



Smartphones



Automotive

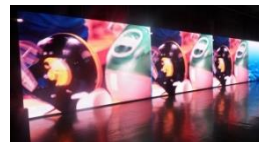


Industrial

General Lighting



Large Display Panel



LED

Dual Camera



3D Sensing



CIS

SMT Solutions

Strong Europe
Market



Industrial



Automotive



China Smartphones

1H/Q2 2018 Group Financial Highlights

	Q2 2018		1H 2018	
	YoY	QoQ	YoY	HoH
Bookings	↑ 10.1%	↓ 3.5%	↑ 16.7%	↑ 38.4%
Billings	↑ 19.1%	↑ 21.3%	↑ 17.5%	↑ 3.0%
Gross Margin	↑ 223bps	↑ 567bps	↑ 17bps	↑ 68bps
EBIT	↑ 31.4%	↑ 58.0%	↑ 22.5%*	↑ 14.7%
Net Profit	↑ 4.1%	↑ 27.0%	↑ 9.4%*	↑ 6.2%
Net Profit Margin	↓ 214bps	↑ 67bps	↓ 108bps*	↑ 44bps

*Excludes adj. of liability component of CB

Q2 2018 Segments Highlights

Q2 2018	Back-end Equipment Segment		Materials Segment		SMT Solutions Segment	
	YoY	QoQ	YoY	QoQ	YoY	QoQ
Bookings	↑ 8.4%	↓ 12.9%	↑ 3.3%	↑ 5.5%	↑ 14.1%	↑ 8.0%
Billings	↑ 17.6%	↑ 28.8%	↑ 7.1%	↑ 2.1%	↑ 26.3%	↑ 17.8%
Gross Margin	↑278bps	↑649bps	↑32bps	↑14bps	↑115bps	↑408bps
Segment Profit	↑31.3%	↑71.6%	↑29.7%	↑14.3%	↑48.2%	↑69.2%
Segment Profit Margin	↑315bps	↑755bps	↑ 131bps	↑80bps	↑275bps	↑565bps

BE Equipment achieved new Billing records in both Q2/1H

Materials Segment set new Billing records in both Q2/1H

BE Equipment achieved GM of 50.8% in Q2, new high since 2010

SMT achieved new Bookings record of US\$570M in 1H

1H 2018 Segments Highlights

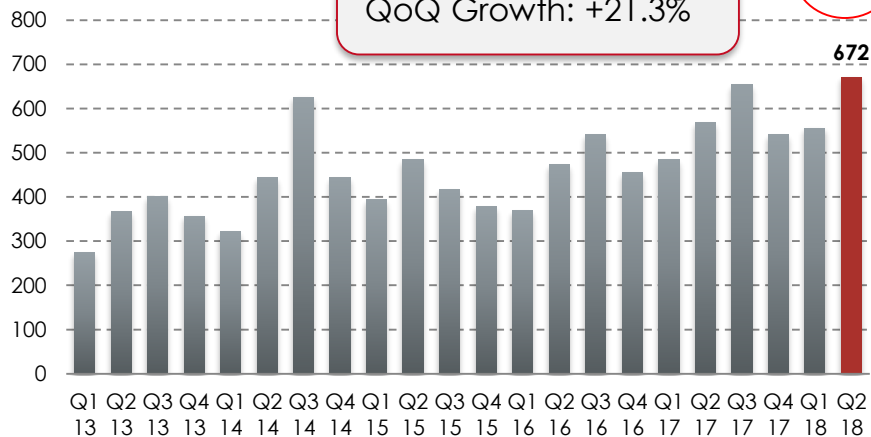
1H 2018	Back-end Equipment Segment		Materials Segment		SMT Solutions Segment	
	YoY	HoH	YoY	HoH	YoY	HoH
Bookings	↑ 16.9%	↑ 60.9%	↓ 7.5%	↑ 12.6%	↑ 25.3%	↑ 22.9%
Billings	↑ 14.4%	↑ 20.1%	↑ 12.1%	↑ 8.7%	↑ 24.6%	↓ 16.4%
Gross Margin	↑59bps	↓59bps	↓38bps	↓35bps	↓40bps	↑117bps
Segment Profit	↑18.6%	↑33.9%	↑12.8%	↑56.3%	↑35.2%	↓ 21.1%
Segment Profit Margin	↑94bps	↑278bps	↑ 5bps	↑217bps	↑126bps	↓96bps

Q2 2018 Group Financial Highlights

Billings
(US\$ m)

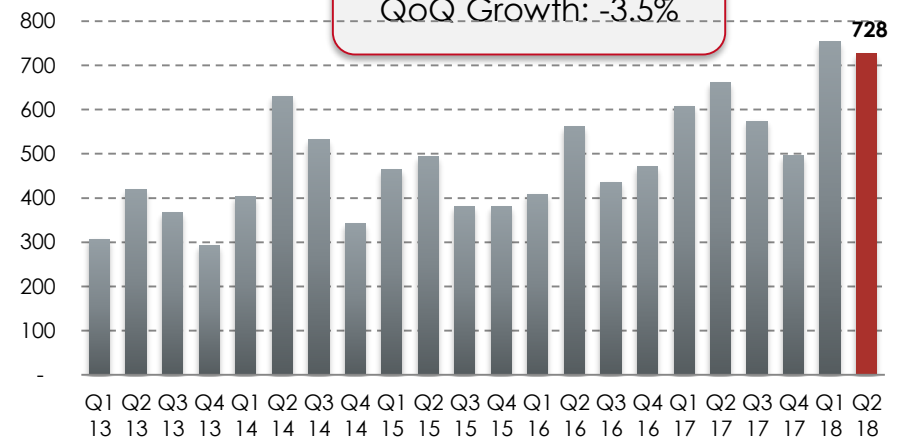
YoY Growth: +19.1%
QoQ Growth: +21.3%

New
Record!

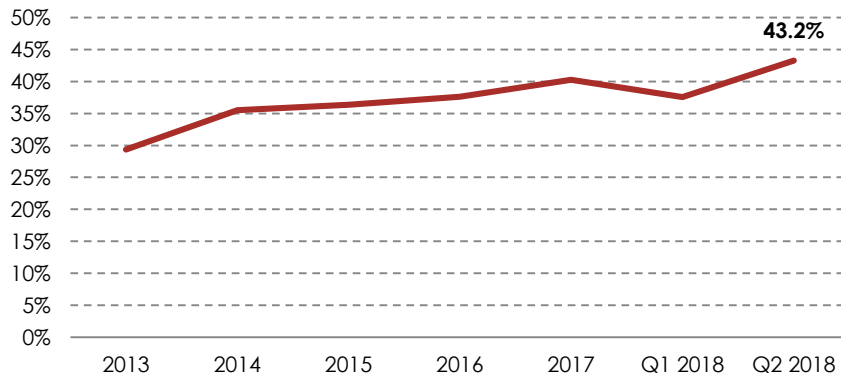


Bookings
(US\$ m)

YoY Growth: +10.1%
QoQ Growth: -3.5%

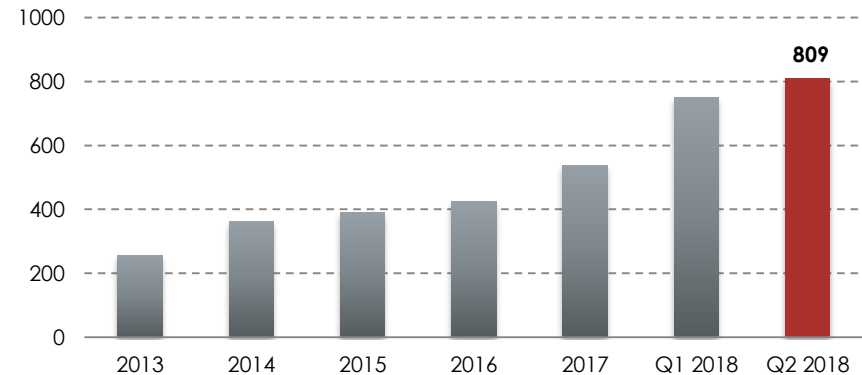


Gross Margin
(%)



Backlog
(US\$ m)

New
Record!

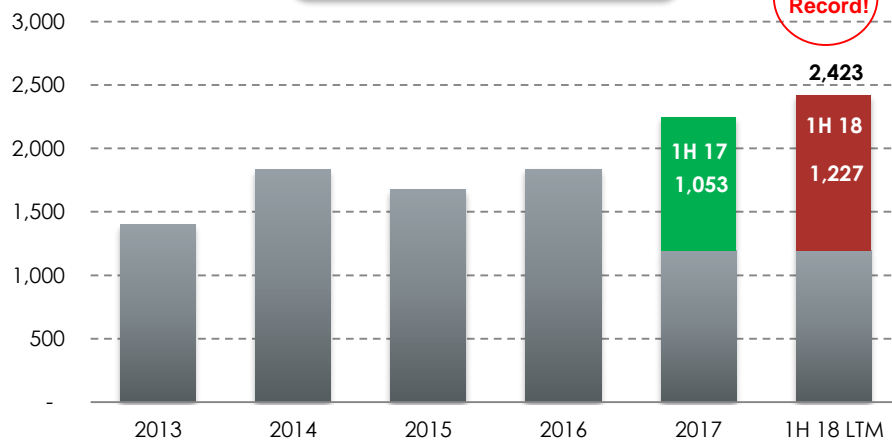


1H 2018 Group Financial Highlights

Billings
(US\$ m)

YoY Growth: +17.5%
HoH Growth: +3.0%

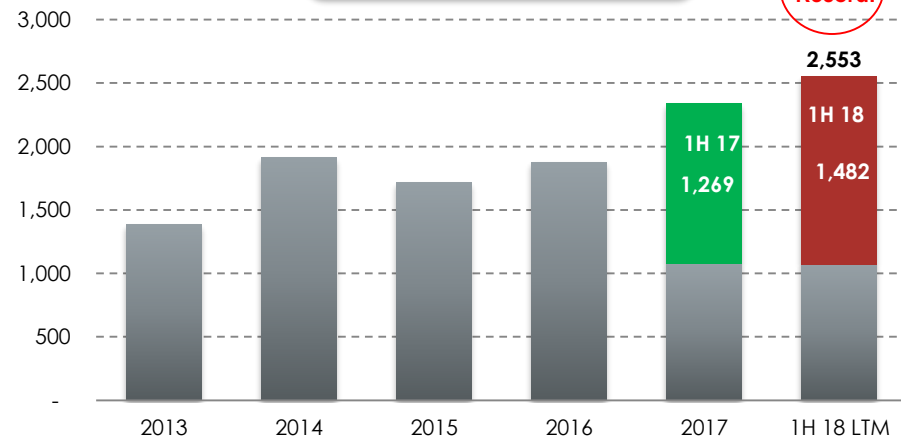
New
Record!



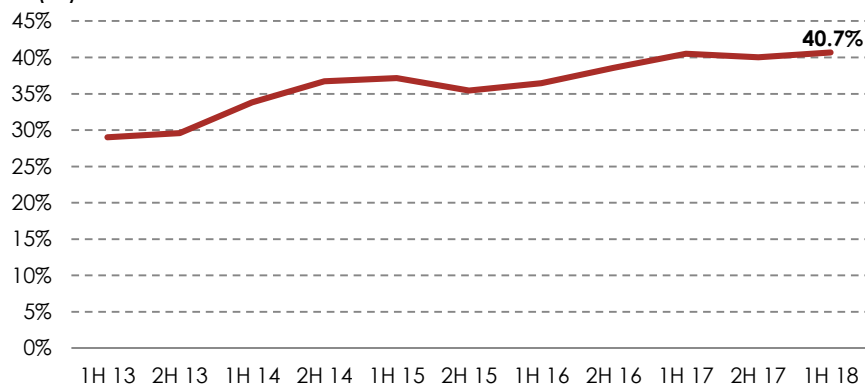
Bookings
(US\$ m)

YoY Growth: +16.7%
HoH Growth: +38.4%

New
Record!



Gross Margin
(%)



- LTM Group Revenue and Bookings hit record levels and amounted to US\$2.42B and US\$2.55B respectively

ASMPT is Well Positioned with expected entry to High Growth Period



Key Strategies for Sustainable Growth & Profitability

GAIN MARKET SHARE

- ❑ Wire bonding
- ❑ Die bonding
- ❑ Lead Frames
- ❑ SMT

INVEST IN NEW GROWTH AREAS

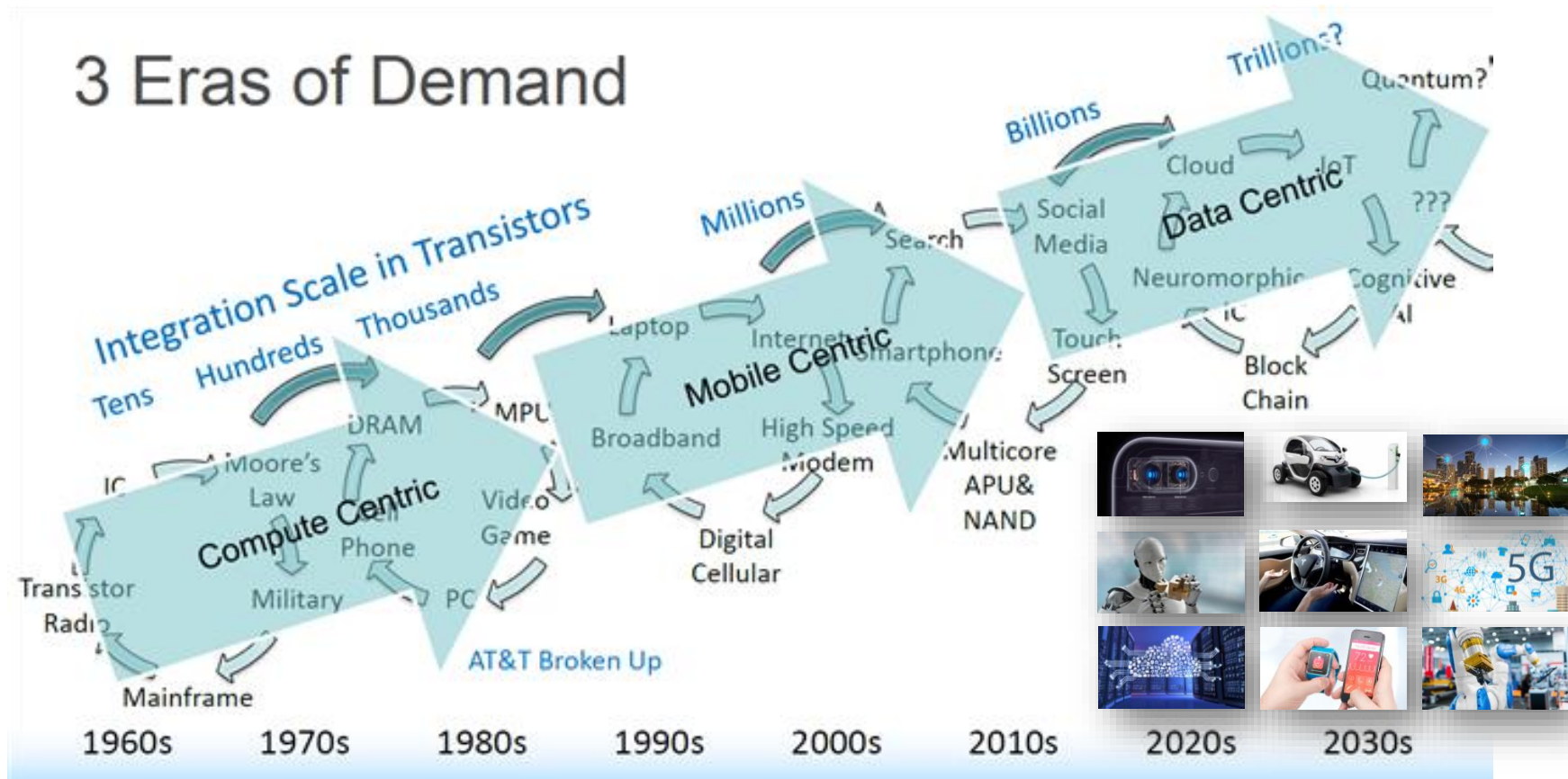
- ❑ CMOS Image Sensor
- ❑ Automotive
- ❑ Power Management
- ❑ Advanced Packaging
- ❑ Data Communication
- ❑ Micro / Mini LED

STRATEGIC M&A

- ❑ SMT Placement
- ❑ SMT Printing
- ❑ LASER Grooving / Dicing
- ❑ MIS
- ❑ AMICRA
- ❑ NEXX

**Continue to Fine-Tune
Organization Structure & Business Strategies**

Dawn of the Data Centric Era

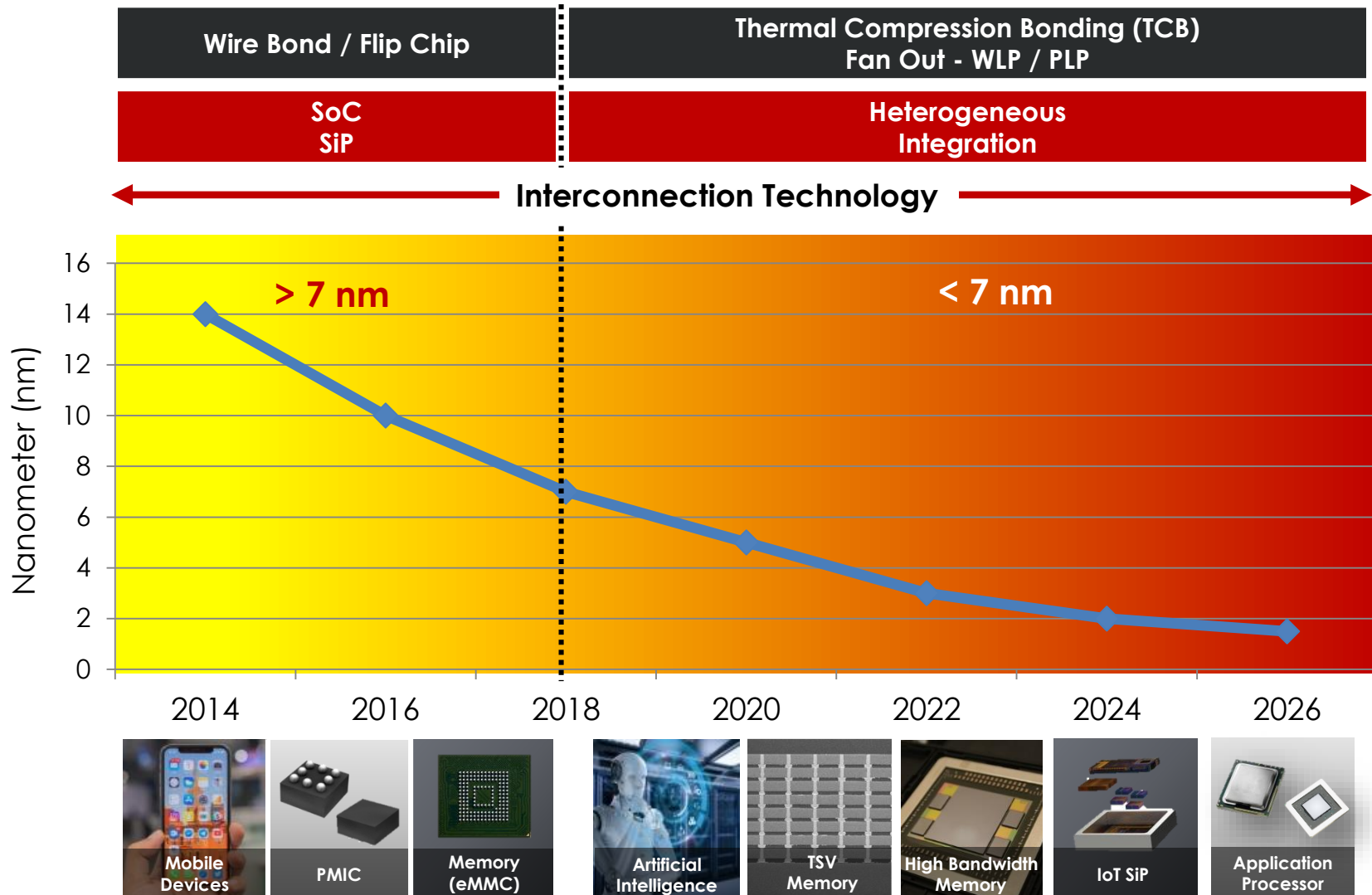


Source: VLSI Research, ISS US, January 2018

Huge amounts of Data will Spur Semiconductor Demand



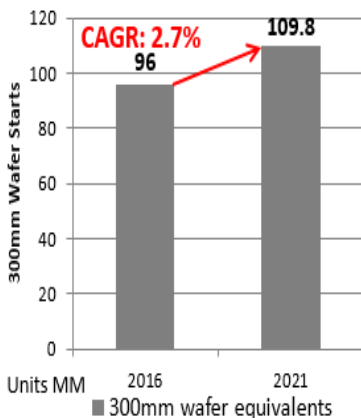
Technology Roadmap - Advanced Packaging



ASMPT is Covering All Interconnection Technologies

Wire Bond

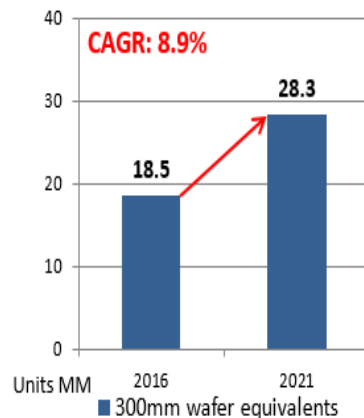
2016-2021



- Wire Bonding
- Die Bonding

Flip Chip

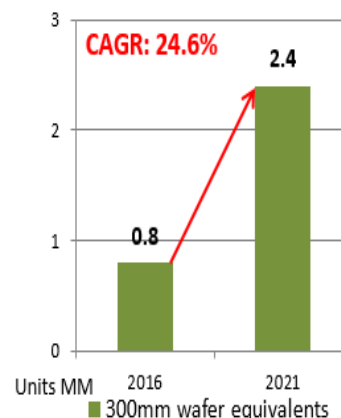
2016-2021



- Flip Chip/NOVA Plus/AFC Plus²
- TCB
- PVD¹
- ECD¹

Fan Out

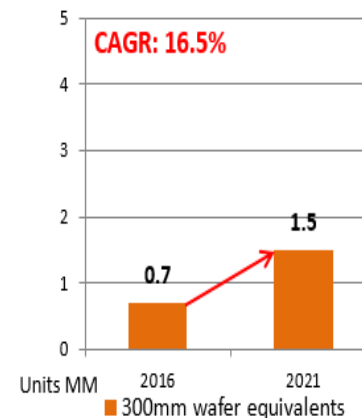
2016-2021



- NUCLEUS/NOVA Plus Fan Out²
- ORCAS
- SUNBIRD
- Laser
- CA
- PVD¹
- ECD¹

3D TSV

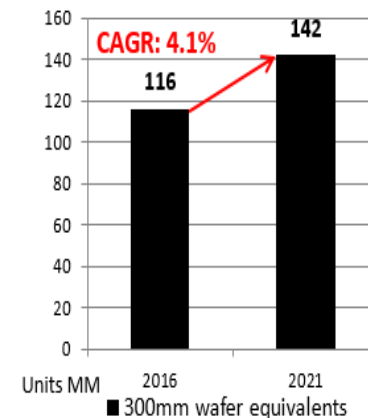
2016-2021



- TCB
- Laser
- PVD¹
- ECD¹

Total Semi. Wafers

2016-2021



Source: Prismark Wafer Starts, 2017

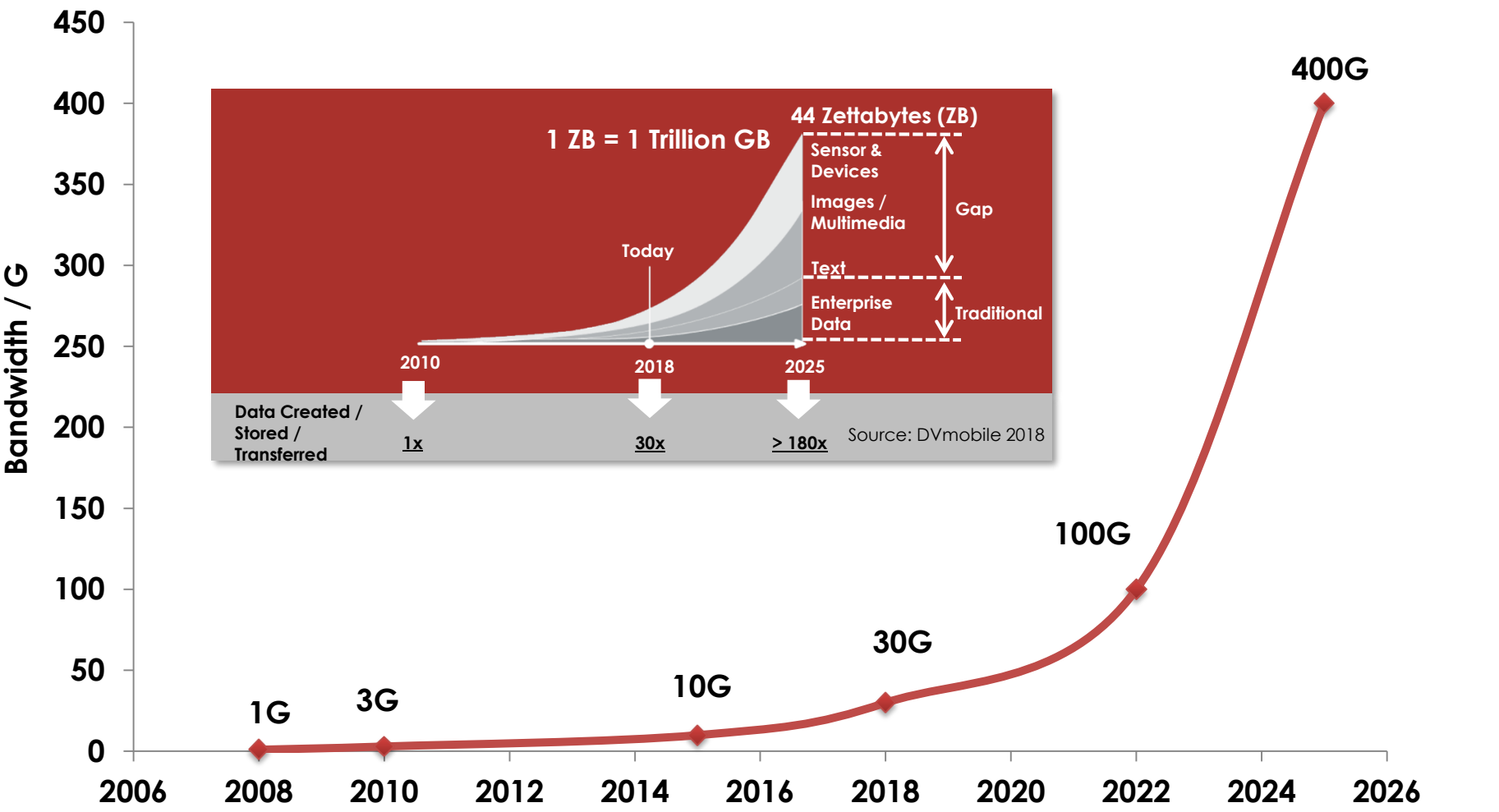
¹ NEXX Product
² AMICRA Product

ASMPT is Recognized by Customers as Leader in Advanced Packaging

- ASMPT is involved in most of our customers' development programs in Advanced Packaging
- ALSI Dicing and Grooving business performed very well this year
 - 1H18 Billings and Bookings had surpassed full year 2017 Billings and Bookings
- TCB has been accepted by more customers
 - Expect some of these customers will reach volume production by next year
 - High Performance Computing (HPC) for AI, finer wafer node technology, and Heterogeneous Integration (HI) may become drivers for wider adoption for TCB
- NUCLEUS pick-and-place equipment has established itself as a definitive benchmark in the WLFO and PLFO markets
 - Highest productivity with accuracy of down to 3 microns plus capability of handling 600mm x 600mm panels
- SUNBIRD, our pick-test-inspect-packing machine for wafer level packages, was one of the contributors to the strong performance of BE equipment business in 1H18
 - Expect demand for SUNBIRD to increase further with introduction of 5G smart phones

DATA is the NEW OIL

Si-Photonics is Key Enabling Technology for High Speed Data Transfer within and between Data Centres



An Unparalleled Product Portfolio for Advanced Packaging



FIREBIRD
(TCB)



SIPLACE CA
(SiP Pick & Place)



NUCLEUS
(FO WLP & PLP – Pick & Place)



ORCAS
(Fan-out Molding)



LASER 1205
(Singulation)



SUNBIRD
(WLP Test & Pack)

Investing Ahead of the Curve



AMICRA NOVA Plus / Fan Out



AMICRA AFC Plus



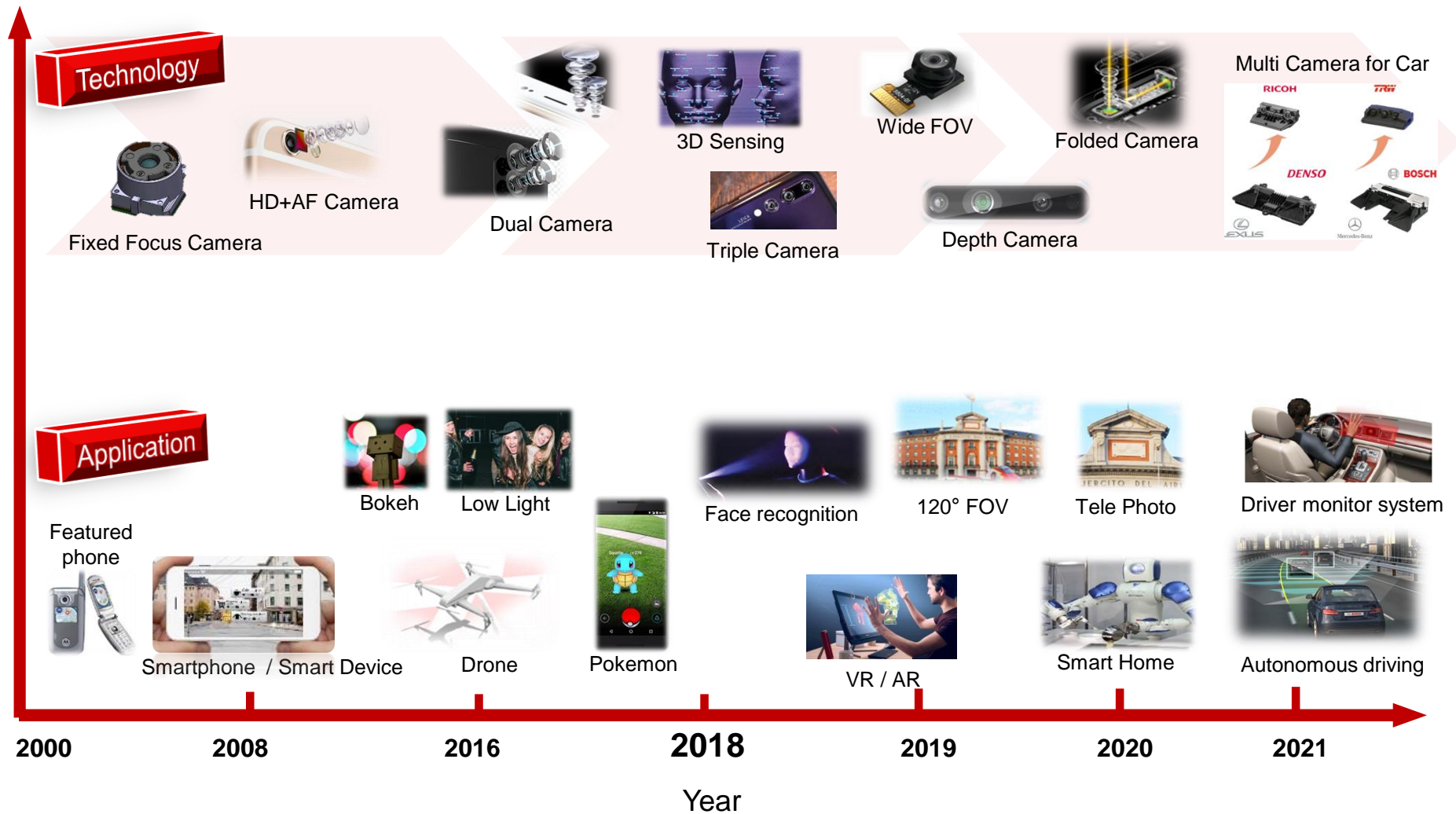
NEXX Conductor FO/FI
(PVD)



NEXX Stratus™ P500
(ECD)



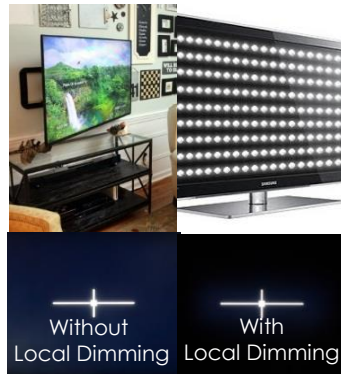
Technology Roadmap for CIS/AA



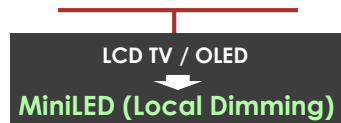
Technology Roadmap for Display Applications



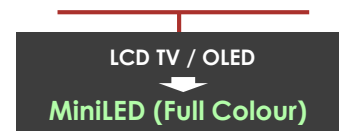
**Wearables
Smartphones | Tablet
Mobile Gadget**



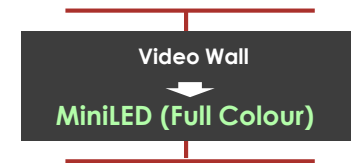
**Small – Mid Size
Displays Backlight
Local Dimming**



**Large Displays with
True RGB color**



**Extra Large Display
Walls with True RGB
color**

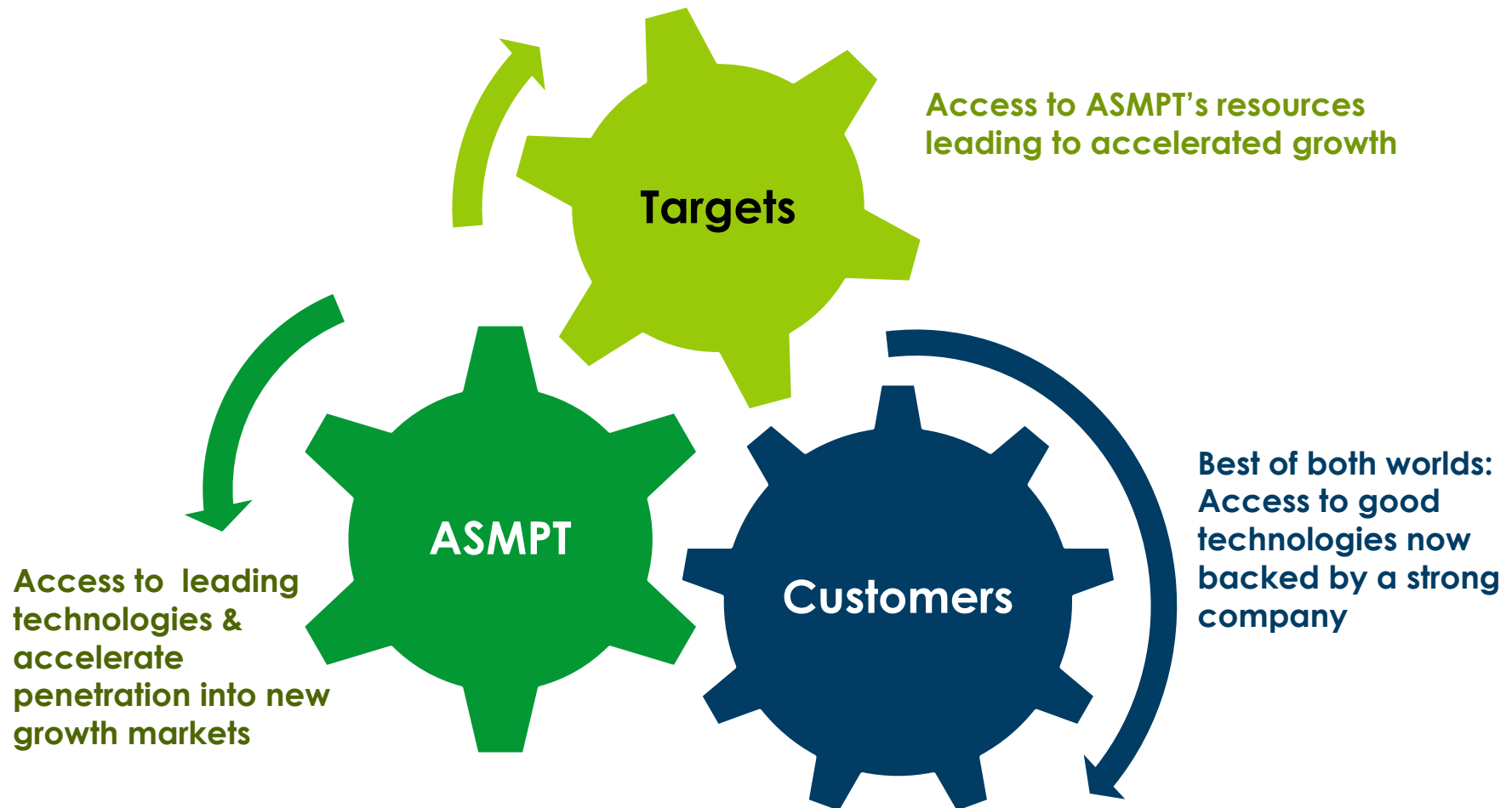


New Target Market for ASMPT -- Memory

- ❑ Wire Bonding System (NAND)
- ❑ LASER Grooving & Dicing (thin wafer)
- ❑ TCB (high bandwidth memory)
- ❑ WLFO / PLFO



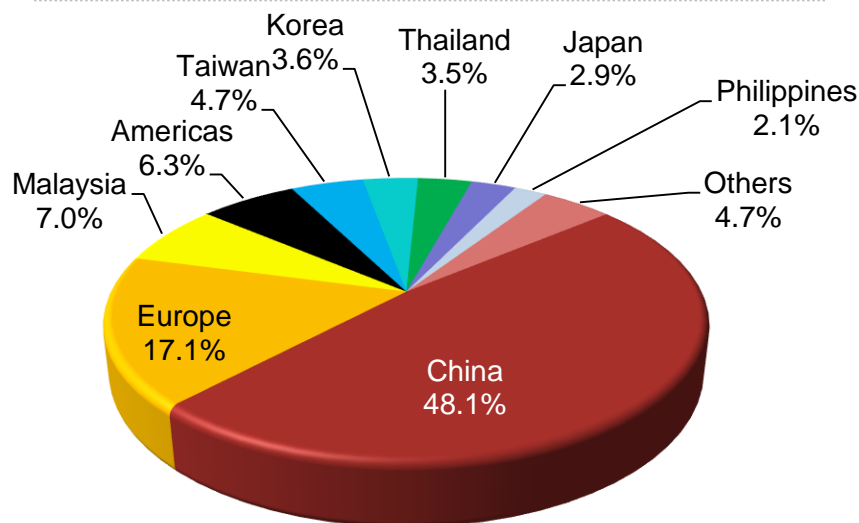
Continuing to Pursue Strategic M&A



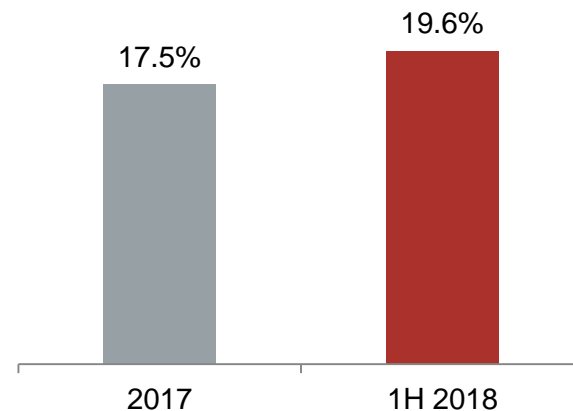
Continue To Build Business On An Extensive Customer Base

- No single customer accounted for more than 10% of the Group's revenue
- Top 5 customers collectively accounted for 19.6% of the Group's 1H 2018 sales revenue
- Top 20 customers include world's leading IDMs, Tier 1 OSAT, major OSATs in China, key LED players, major camera module makers, top EMS providers, and leading automotive component suppliers
- Among the top 20 customers of the Group, 4 were from SMT Solutions segment, and 3 were key customers from both Back-end business and SMT Solutions segment

1H 2018 Geographical Distribution of Revenue



1H 2018 Revenue Contribution from Top 5 Customers

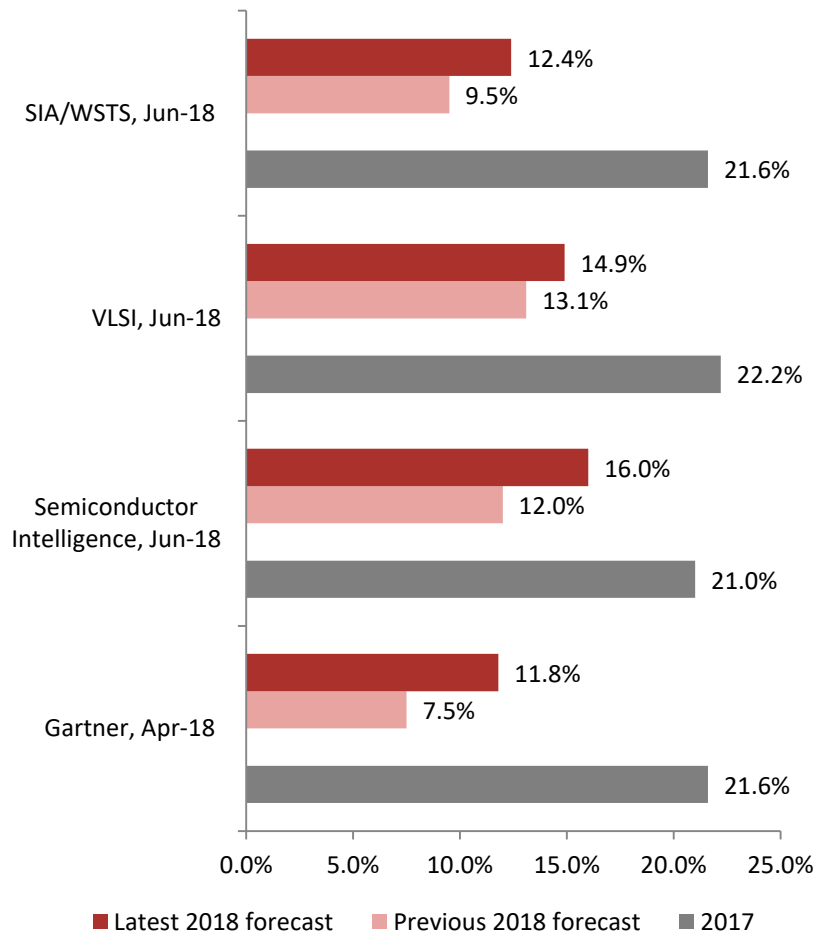


OUTLOOK

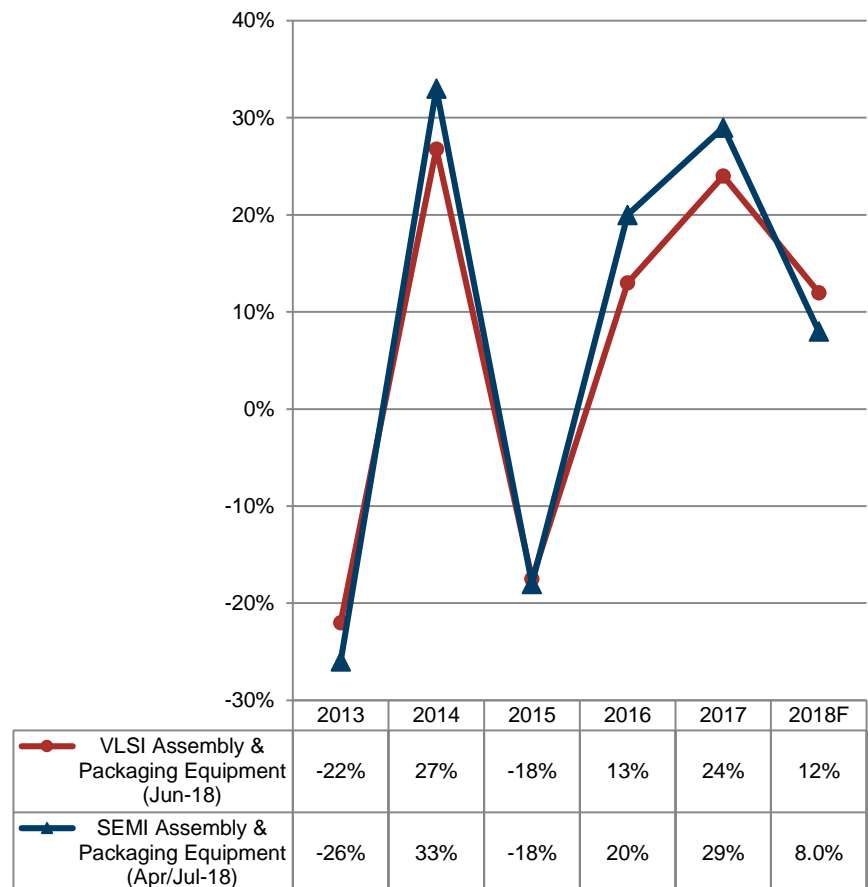


Industry Growth Forecast (2017-2018)

Semiconductor Industry



Forecast Global Assembly & Packaging Equipment Market

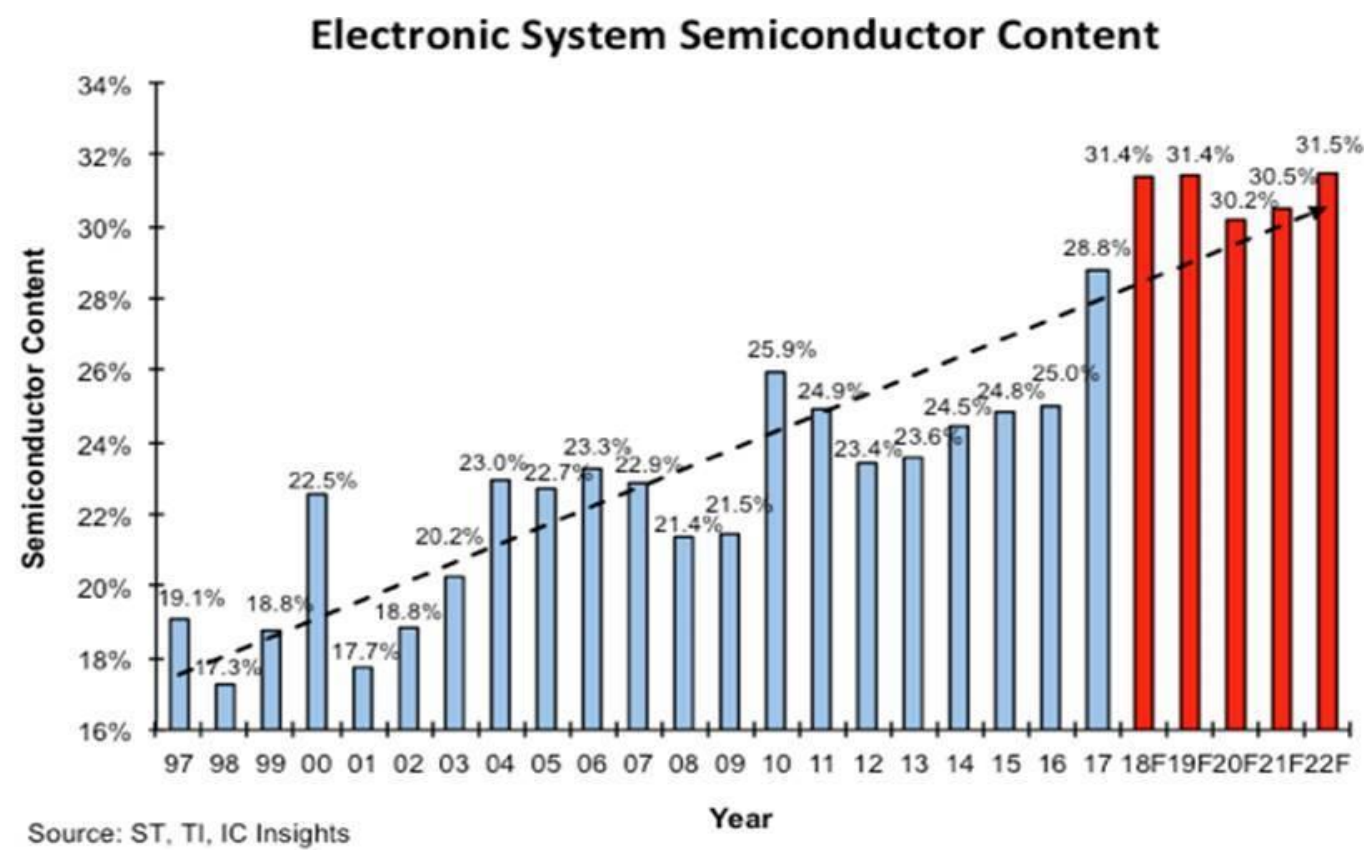


Semiconductor Industry Growth Forecast (2018-2019)

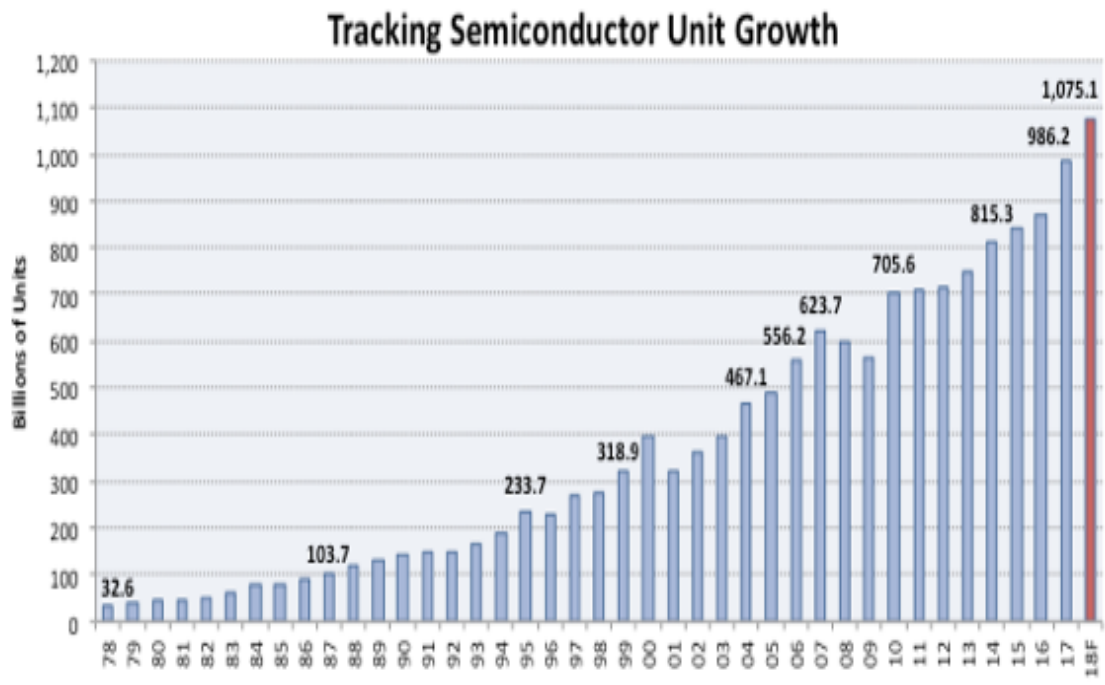
YoY Growth	2018F		2019F
	<i>Revised</i>	<i>Previous</i>	<i>Initial</i>
Americas	14.0% ↓	16.8%	4.6%
Europe	13.4% ↑	6.6%	4.7%
Japan	8.6% ↑	6.6%	4.2%
Asia Pacific	12.3% ↑	7.7%	4.3%
Total World	12.4% ↑	9.5%	4.4%
Discrete	9.0% ↑	6.7%	4.4%
Optoelectronics	3.4% ↓	11.1%	5.7%
Sensors	5.8% ↓	8.0%	6.1%
Integrated Circuits	13.8% ↑	9.5%	4.2%
Analog	9.5% ↑	8.1%	5.1%
Micro	3.5% ↓	7.1%	3.7%
Logic	7.1% ↓	9.3%	4.8%
Memory	26.5% ↑	11.6%	3.7%
Total Products	12.4% ↑	9.5%	4.4%

Source: SIA/WSTS, June 2018

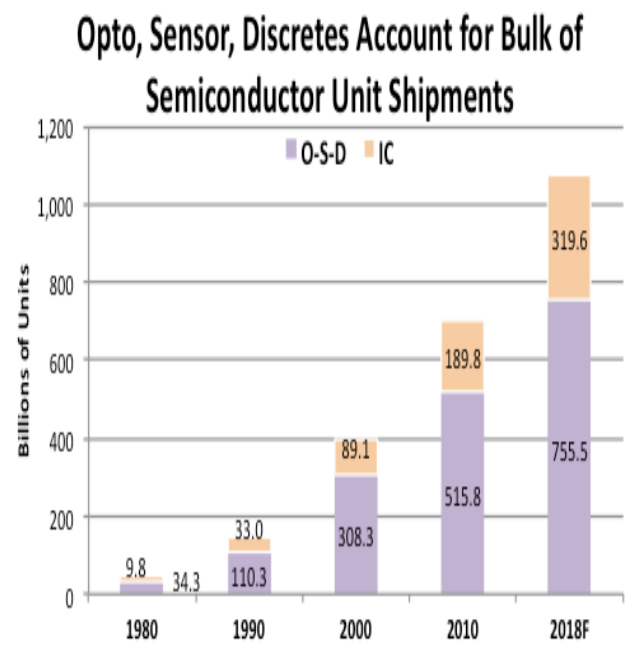
Semi Content in Electronic Systems Forecast to Reach 31.4% in 2018



Semiconductor Shipments Forecast to Exceed 1 Trillion Devices in 2018



Source: IC Insights, January 2018



Outlook

- Expect 2018 to be a year of growth for the Group compared with 2017 and anticipate Group Billings to set new record
 - Unless market conditions deteriorate drastically in 2H18
- Anticipate Q3 Group Billings to be in range of US\$650M-US\$700M, given the strong backlog
 - Expect QoQ improvement for SMT Billings, with increased contribution from Asian market for SMT in Q3 in line with typical seasonal pattern for this segment and our momentum in China/India
 - BE equipment Billings may experience small decline from the peak achieved in Q2
 - Materials Billings expected to be flat compared with Q2
- Expect Group Bookings in Q3 to be lower QoQ due to typical seasonal effects
 - Difficult to work out reliable forecast due to uncertain global economic and political circumstances
- Expect Group GM may decline by 1.5%-3% from Q2 18 due to product/geographical mix
- On a longer term basis, believe we are entering into an exciting era of the industry and a high growth period for ASMPT
- Industry being driven by diversified growth drivers and ASMPT is well positioned to capture those opportunities

ASMPT Sustainable Competitive Advantages

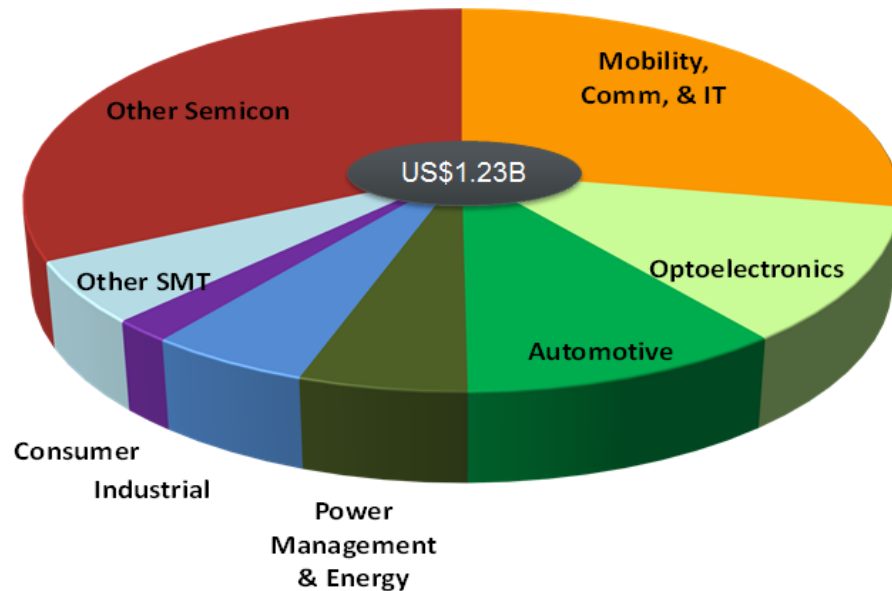
- Multiple product growth drivers (and a strong leader in a few of these drivers including CIS/AA, LED, Automotive, TCB)
- Diversified product portfolio addressing multiple applications markets
- Unique and comprehensive product portfolio in Advanced Packaging
- Broad and diverse customer base
- Breadth and depth of enabling technologies
- Investing ahead of the curve and bearing fruits
- Strong and extensive marketing/support network
- Size, scale and strong balance sheet & financial resources
- Steadfast execution of strategies
- Keep reinventing itself



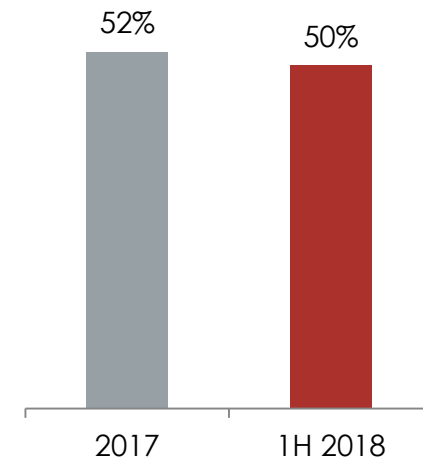
2018 Q2 FINANCIAL RESULTS



ASMPT Revenue Breakdown by Application Markets (1H 18)



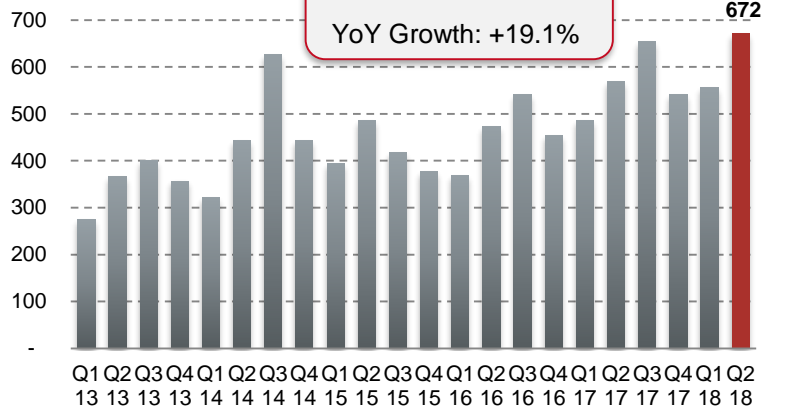
Mobility, Comm & IT, Optoelectronics and Automotive % of Group Revenue



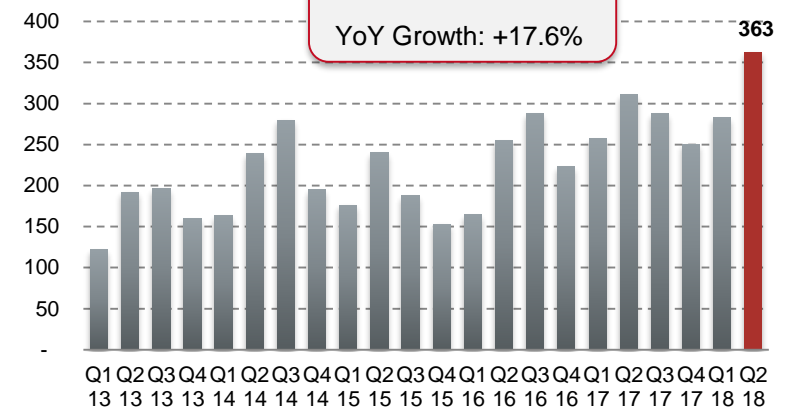
Multiple Application Markets is a key strategy

Q2 2018 Quarterly Billings

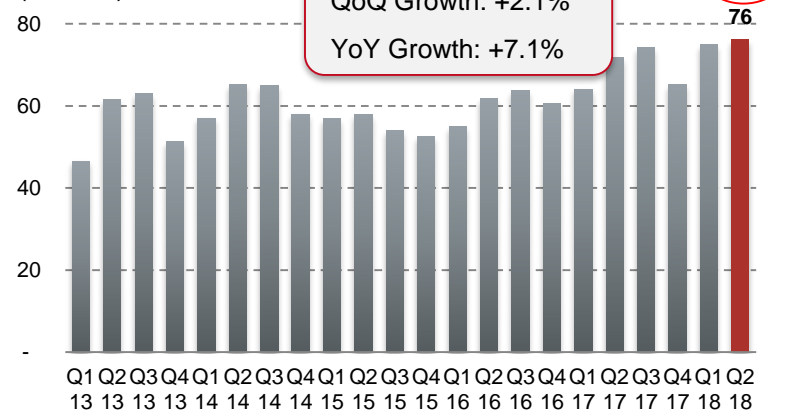
Group Billings
(US\$ m)



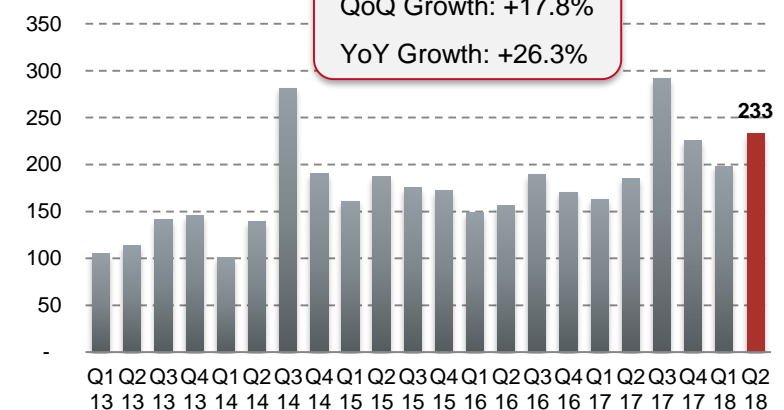
BE EQT Billings
(US\$ m)



Materials Billings
(US\$ m)

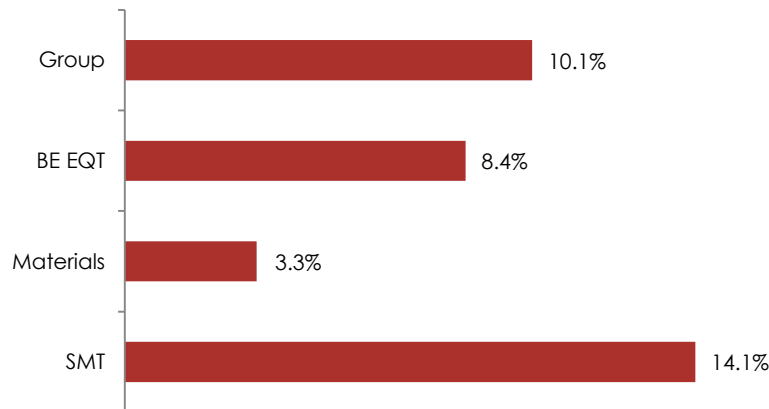


SMT Billings
(US\$ m)

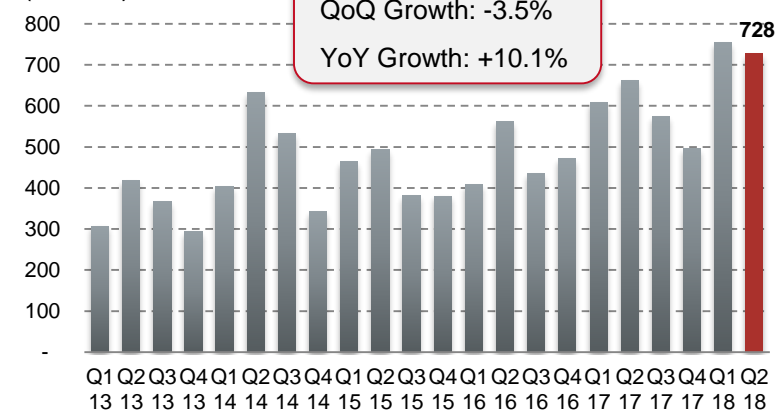


Q2 2018 Booking, Backlog and Segment Profits

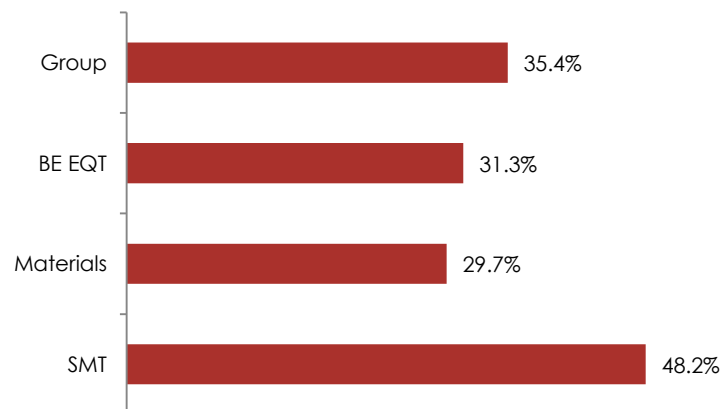
Q2 2018 Booking
(YoY % Growth)



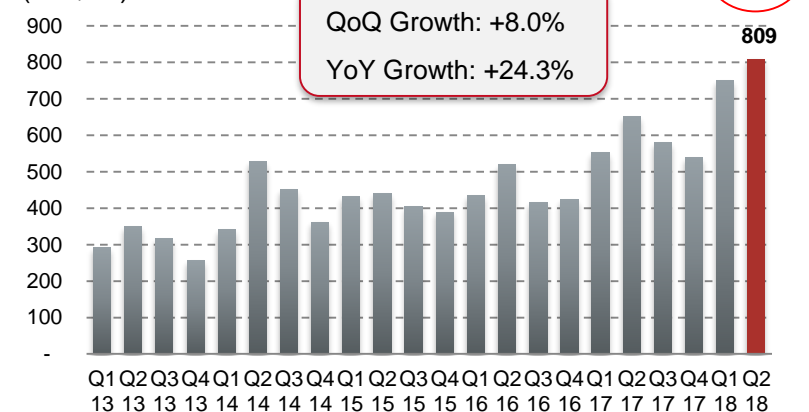
Quarterly Group Bookings
(US\$ m)



Q2 2018 Segment Profits
(YoY % Growth)



Quarterly Group Backlog
(US\$ m)



1H/Q2 2018 Segment Results – Back-End Equipment Business

	Q2 2018	QoQ	YoY	1H 2018	HoH	YoY
Bookings (USD)	354.2m	↓ 12.9%	↑ 8.4%	760.9m	↑ 60.9%	↑ 16.9%
Billings (USD)	362.7m	↑ 28.8%	↑ 17.6%	645.3m	↑ 20.1%	↑ 14.4%
Gross Margin	50.8%	↑ 649bps	↑ 278bps	48.0%	↓ 59bps	↑ 59bps
Segment Profit (HKD)	861.9m	↑ 71.6%	↑ 31.3%	1,364m	↑ 33.9%	↑ 18.6%
Segment Profit Margin	30.3%	↑ 755bps	↑ 315bps	27.0%	↑ 278bps	↑ 94bps

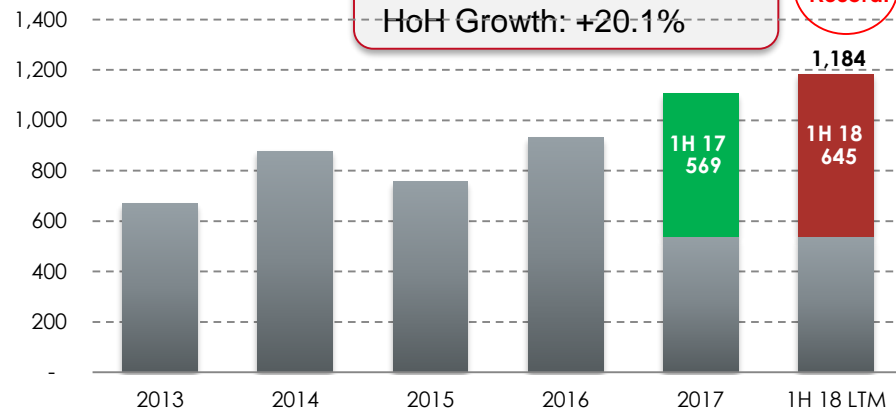
1H/Q2 2018 Segment Results – Back-End Equipment Business

Yearly Billings
(US\$ m)

YoY Growth: +14.4%

HoH Growth: +20.1%

New
Record!

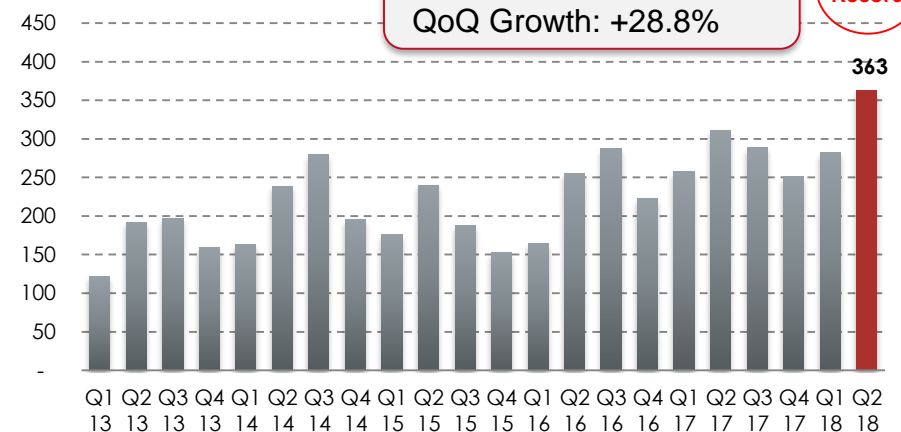


Quarterly Billings
(US\$ m)

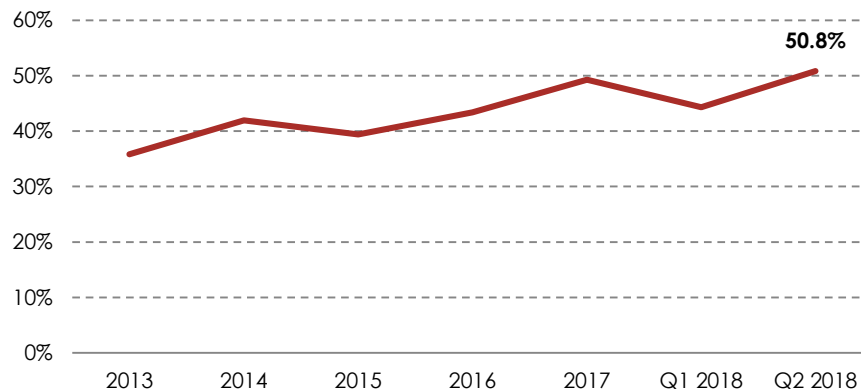
YoY Growth: +17.6%

QoQ Growth: +28.8%

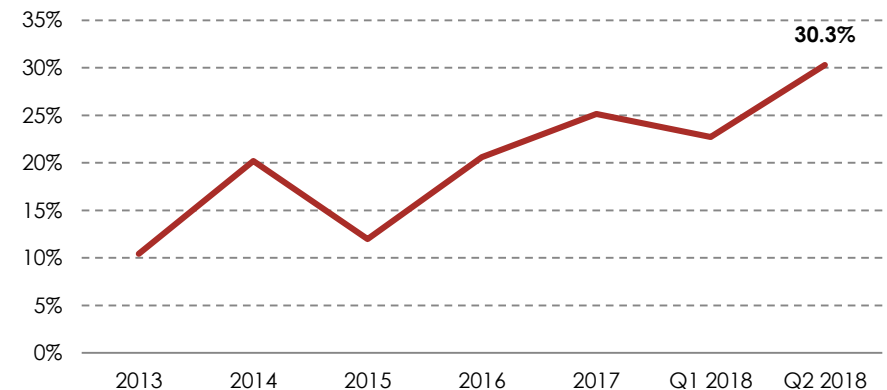
New
Record!



Gross Margin
(%)



Segment Profit Margin
(%)

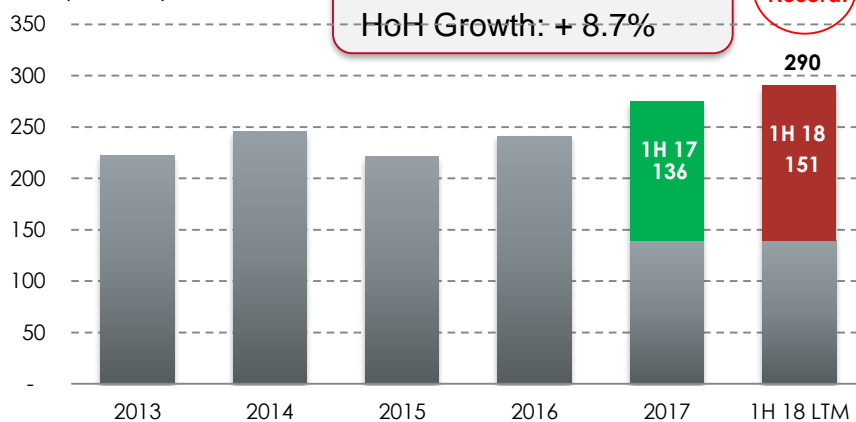


1H/Q2 2018 Segment Results – Materials Business

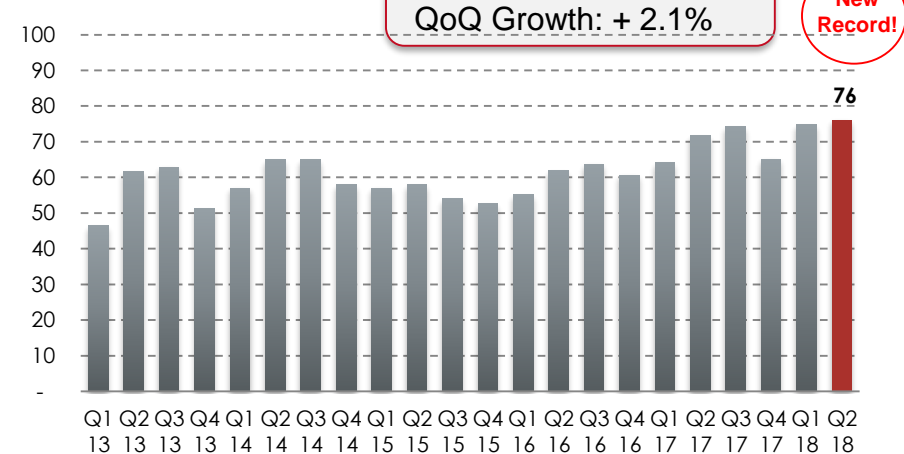
	Q2 2018	QoQ	YoY	1H 2018	HoH	YoY
Bookings (USD)	77.5m	↑ 5.5%	↑ 3.3%	150.9m	↑ 12.6%	↓ 7.5%
Billings (USD)	76.1m	↑ 2.1%	↑ 7.1%	151.0m	↑ 8.7%	↑ 12.1%
Gross Margin	13.3%	↑ 14bps	↑ 32bps	13.2%	↓ 35bps	↓ 38bps
Segment Profit (HKD)	44.9m	↑ 14.3%	↑ 29.7%	84.1m	↑ 56.3%	↑ 12.8%
Segment Profit Margin	7.5%	↑ 80bps	↑ 131bps	7.1%	↑ 217bps	↑ 5bps

1H/Q2 2018 Segment Results – Materials Business

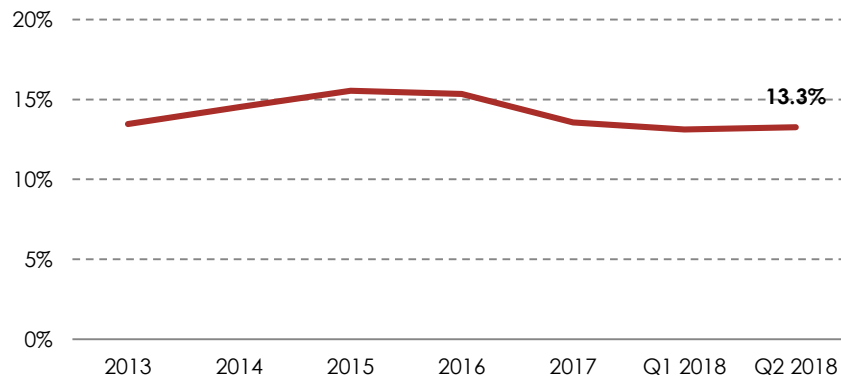
Yearly Billings
(US\$ m)



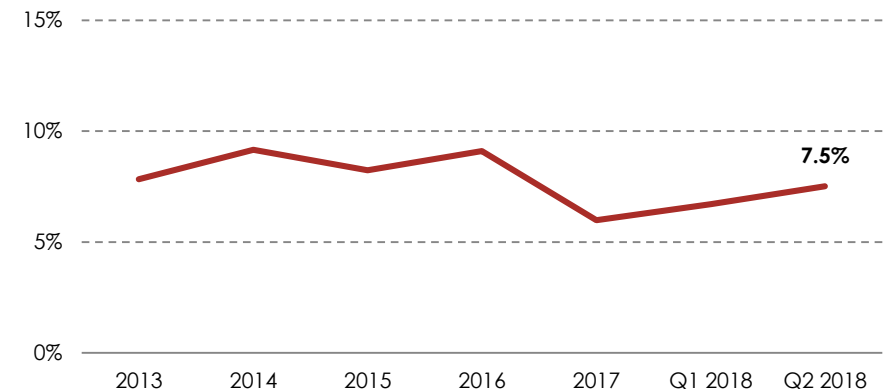
Quarterly Billings
(US\$ m)



Gross Margin
(%)



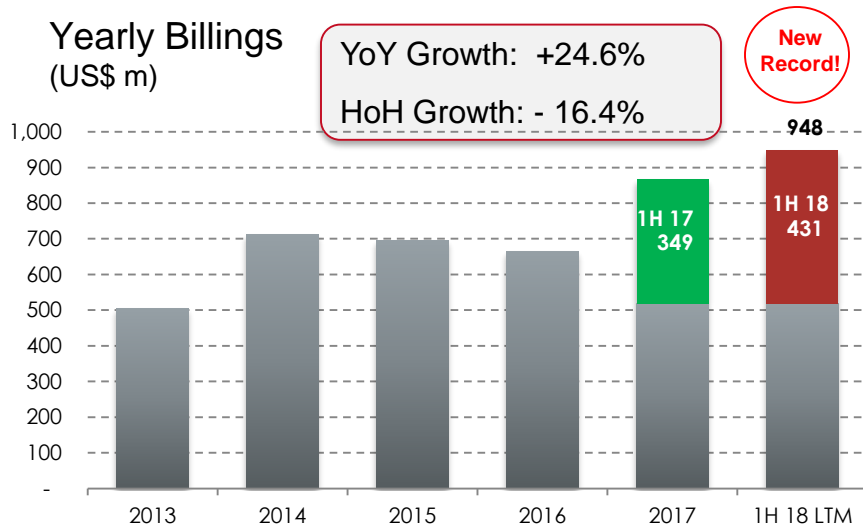
Segment Profit Margin
(%)



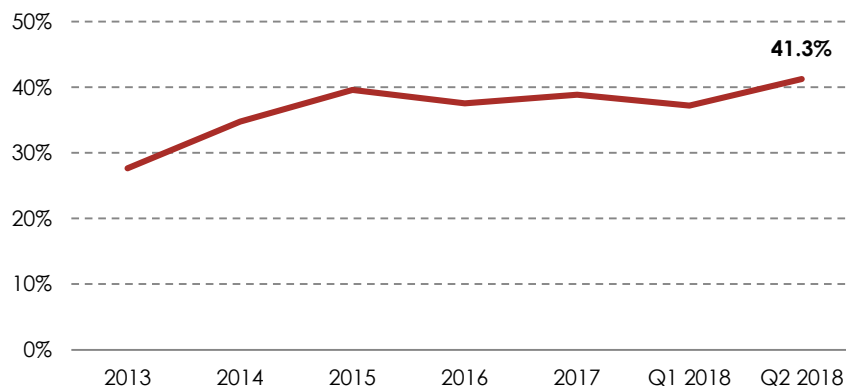
1H/Q2 2018 Segment Results – SMT Solutions Business

	Q2 2018	QoQ	YoY	1H 2018	HoH	YoY
Bookings (USD)	296.1m	↑ 8.0%	↑ 14.1%	570.1m	↑ 22.9%	↑ 25.3%
Billings (USD)	232.7m	↑ 17.8%	↑ 26.3%	431.0m	↓ 16.4%	↑ 24.6%
Gross Margin	41.3%	↑ 408bps	↑ 115bps	39.4%	↑ 117bps	↓ 40bps
Segment Profit (HKD)	339.5m	↑ 69.2%	↑ 48.2%	540.2m	↓ 21.1%	↑ 35.2%
Segment Profit Margin	18.6%	↑ 565bps	↑ 275bps	16.0%	↓ 96bps	↑ 126bps

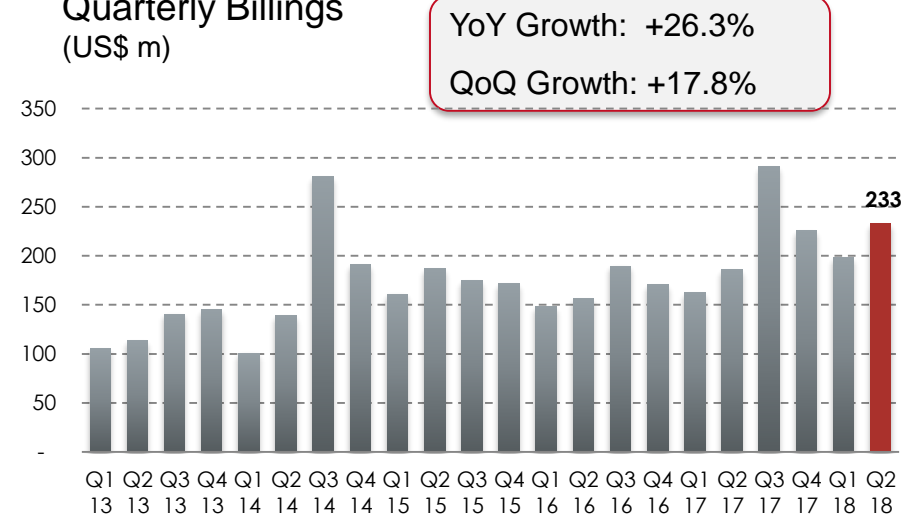
1H/Q2 2018 Segment Results – SMT Solutions Business



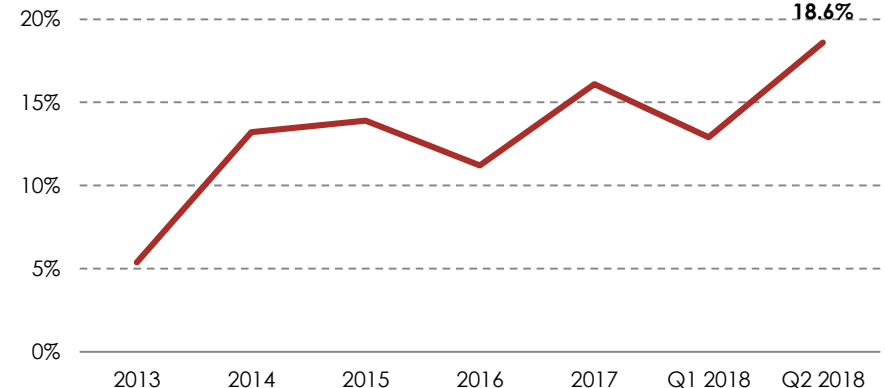
Gross Margin (%)



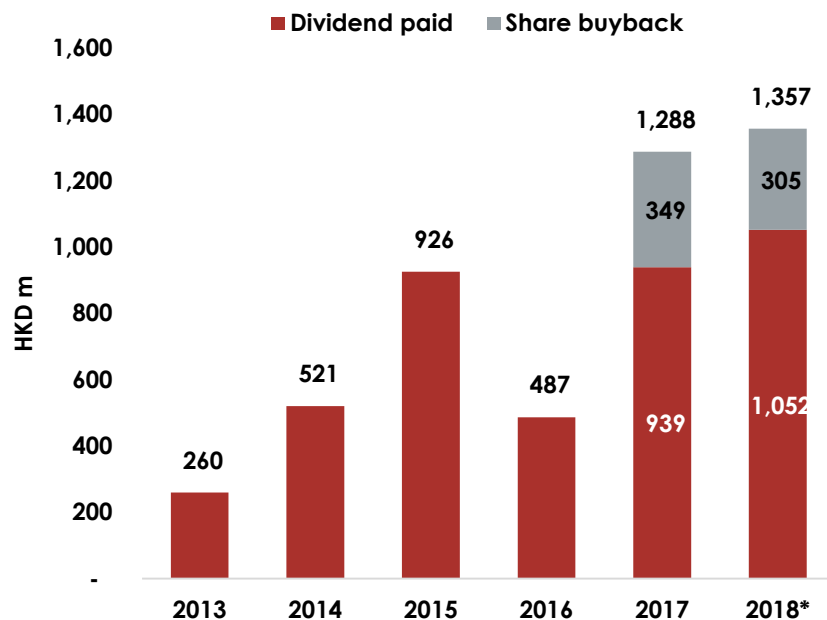
Quarterly Billings (US\$ m)



Segment Profit Margin (%)



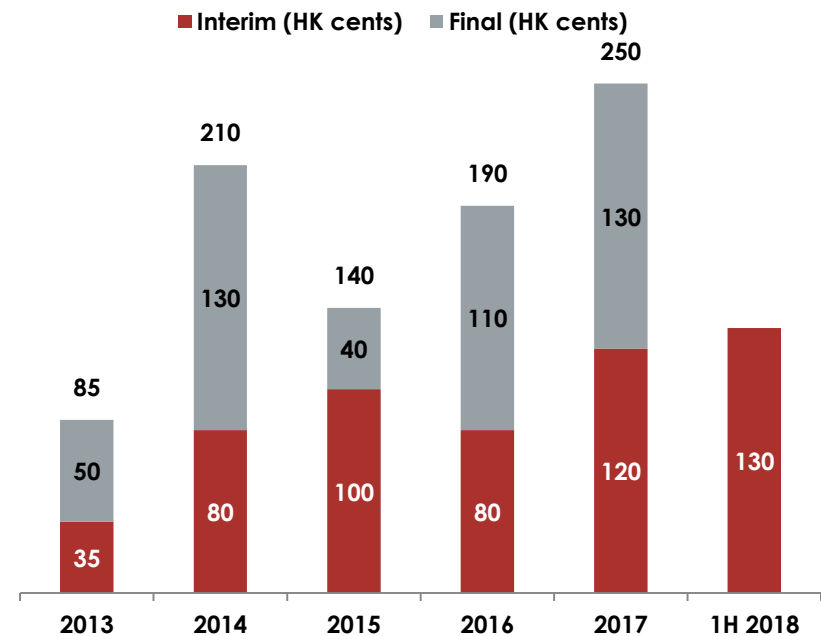
Return of Capital to Shareholders



Cumulative cash returned: HKD4.8B

* Per Year-to-date share repurchased, paid dividend and proposed interim DPS of HKD1.30

Dividend Per Share (HK cents)



Share Buyback Program

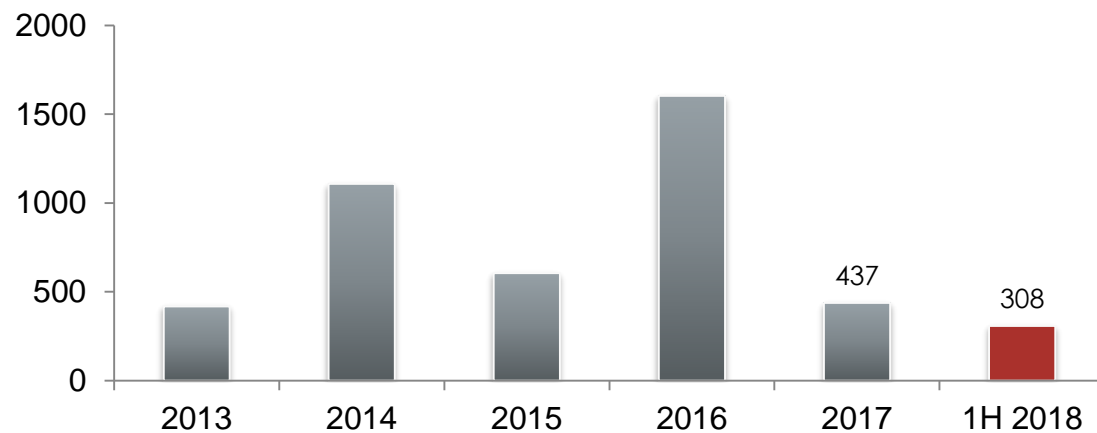
- Repurchased 6,056,400 shares from Sep 2017 to Jun 2018 for a consideration of HK\$654.1M

Cash Dividend Policy

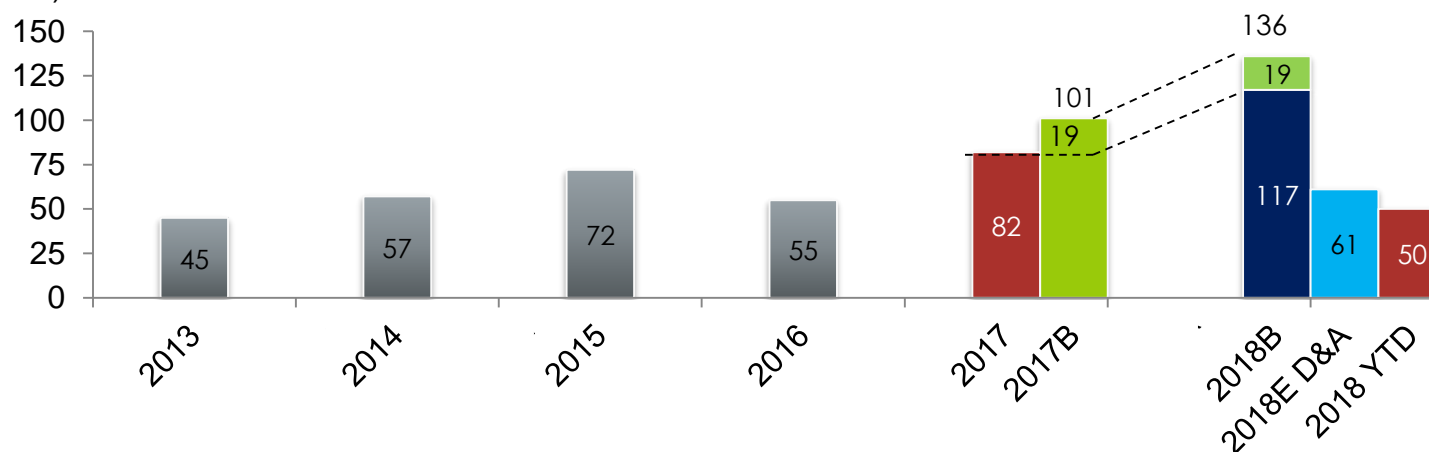
- Sustainable and gradually increasing

Free Cash Flow and Capital Investment

Free Cash Flow
(HK\$ m)

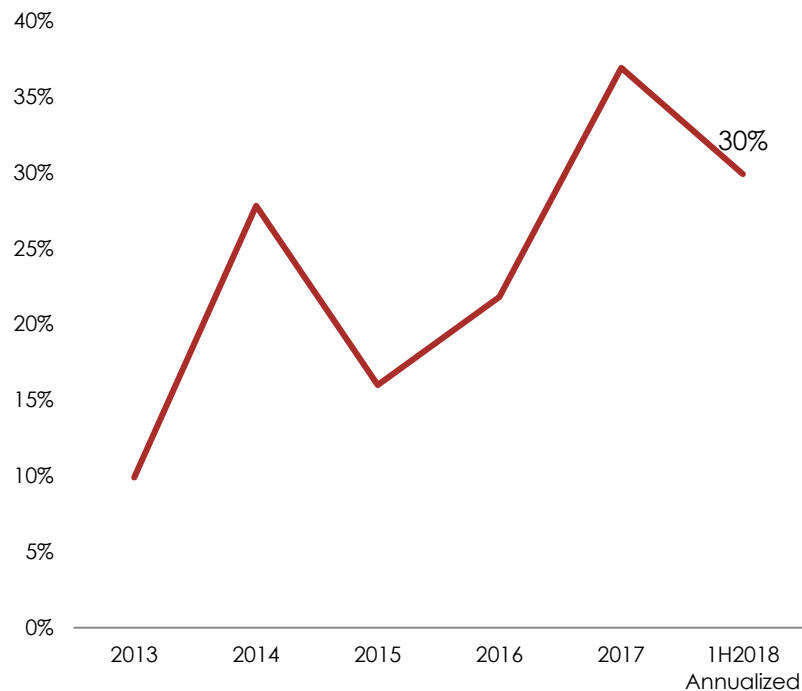


Capital Investment
(US\$ m)

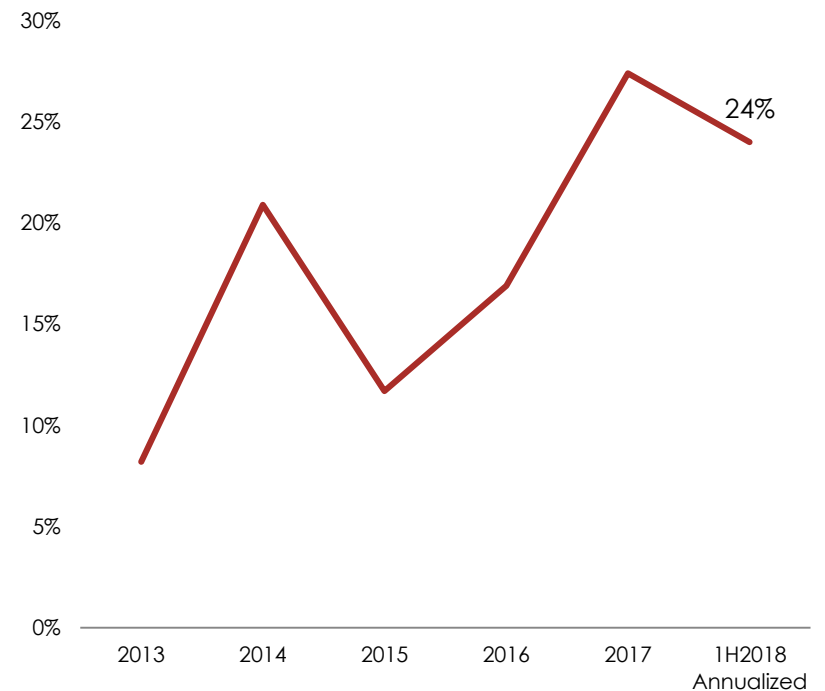


Financial Metrics

Return On Invested Capital (ROIC)

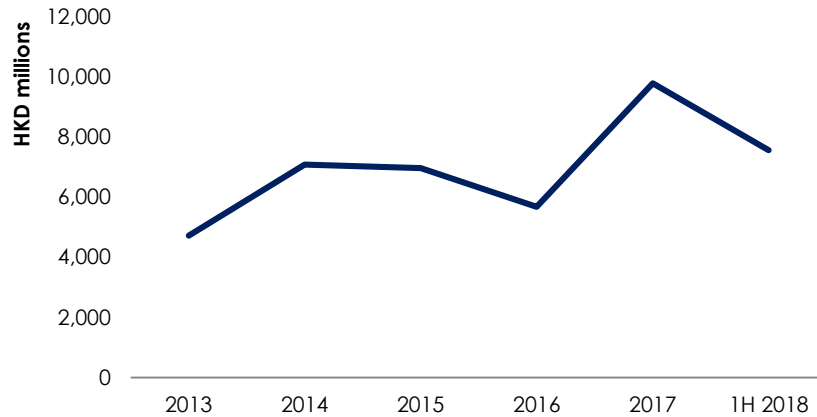


Return On Equity (ROE)

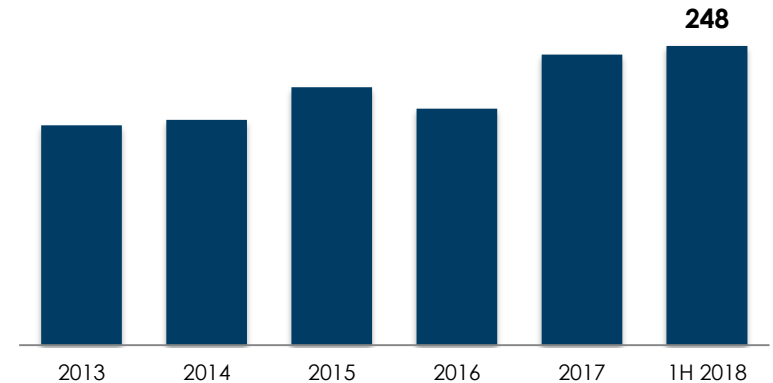


Working Capital Management

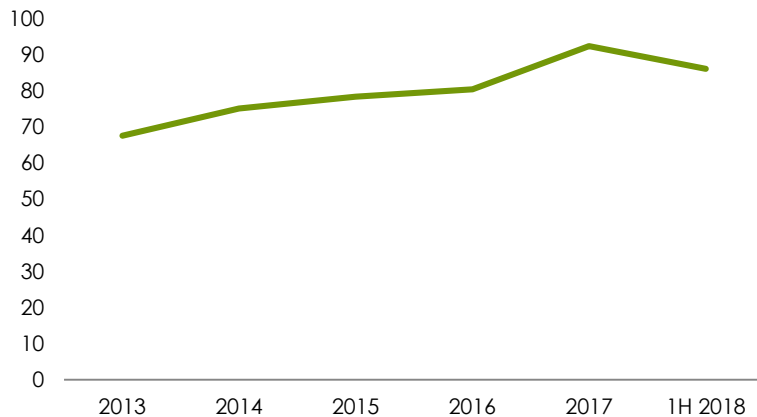
Working Capital



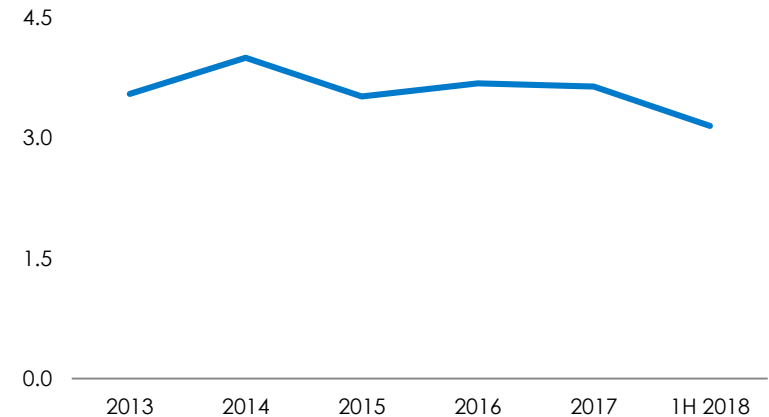
Cash Conversion Cycle (Days)



Days Sales Outstanding*



Inventory Turnover



*Excludes notes receivables

AWARDS & RECOGNITION



Recent Awards & Recognition

- Technology Achievement Grand Award of HKIA 2017
(for the third time)
Federation of HK Industries



- Directors of the Year Awards 2017
Hong Kong Institute of Directors



- Hong Kong Outstanding Enterprises 2017
HK Economic Digest



- 2017 All Stars of the Semiconductor Industry
VLSI Research

VLSIresearch's 2017 All Stars

Recent Awards & Recognition

- Factory of the Year 2016 Award (for SMT) by Produktion/AT Kearney



- Ranked among Top 10 of Best Managed HK Companies
- Ranked among Top 10 of Best at Investor Relations



- 2017 & 2018 “Triple Crown” with RANKED 1st/10 BEST/THE BEST Suppliers Awards from VLSIresearch



- 2016-17 Corporate Governance Asia – Best Investor Relations Company (HK)
- 2017 Corporate Governance Asia – Best CEO (Investor Relations)



- 2015 Hong Kong Awards for Industries: Technology Achievement Grand Award



VLSI Awards 2018

				
10 BEST Segment	Rank	10 BEST CHIP MAKING EQUIPMENT SUPPLIERS OF 2018	Rating	Stars
LARGE	1	TERADYNE	9.25	★★★★★
	2	ADVANTEST	9.10	★★★★★
	3	ASML	9.05	★★★★★
	4	Hitachi Kokusai Electric	8.90	★★★★★
	5	TEL	8.45	★★★★★
	6	APPLIED MATERIALS	7.55	★★★★★
	7	ASM Pacific Technology	7.45	★★★
	8	Hitachi High-Tech	7.45	★★★
FOCUSED	1	Plasma Therm	9.01	★★★★★
	2	AMEC	8.95	★★★★★
	3	FORMFACTOR	8.94	★★★★★
	4	SPTS	8.90	★★★★★
	5	Xcerra	8.76	★★★★★
	6	EVG	8.42	★★★★★
	7	ACCRETECH TOKYO SEIMITSU	7.22	★★★

			WHAT THE BEST SUPPLIERS OF 2018 ARE BEST AT	
ACCRETECH	TOKYO SEIMITSU	<ul style="list-style-type: none"> Uptime Usable Performance 	ADVANTEST	<ul style="list-style-type: none"> Trust in Supplier Recommend Supplier
AMEC		<ul style="list-style-type: none"> Recommend Supplier Trust in Supplier 	APPLIED MATERIALS	<ul style="list-style-type: none"> Field Engineering Support Uptime
ASM Pacific Technology		<ul style="list-style-type: none"> Field Engineering Support Support After Sales 	ASML	<ul style="list-style-type: none"> Recommend Supplier Technical Leadership
EVG		<ul style="list-style-type: none"> Technical Leadership Trust in Supplier 	FORMFACTOR	<ul style="list-style-type: none"> Technical Leadership Recommend Supplier
Hitachi High-Tech		<ul style="list-style-type: none"> Trust in Supplier Uptime 	Hitachi Kokusai Electric	<ul style="list-style-type: none"> Field Engineering Support Process Support
JAPAN ELECTRONIC MATERIALS		<ul style="list-style-type: none"> Partnering Recommend Supplier 	Nidec SVTCL	<ul style="list-style-type: none"> Partnering Commitment
Plasma Therm		<ul style="list-style-type: none"> Trust in Supplier Spares Support 	SPTS	<ul style="list-style-type: none"> Recommend Supplier Uptime
TECHNOPROBE		<ul style="list-style-type: none"> Support After Sales Trust in Supplier and Partnering 	TERADYNE	<ul style="list-style-type: none"> Trust in Supplier Recommend Supplier
TEL		<ul style="list-style-type: none"> Trust in Supplier Uptime 	Xcerra	<ul style="list-style-type: none"> Trust in Supplier Recommend Supplier

			RATINGS FOR THE BEST SUPPLIERS OF 2018		
ASSEMBLY EQUIPMENT		Rating	VLSI STARS		
1	ASM Pacific Technology	7.47	★★★		

ENABLING THE DIGITAL WORLD

